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Top Story

HP to Acquire EDS for \$13.9 Billion

13 May 2008

HP and EDS today announced that they have signed a definitive agreement under which HP will purchase EDS at a price of \$25.00 per share, or an enterprise value of approximately \$13.9 billion. The terms of the transaction have been unanimously approved by the HP and EDS boards of directors.

The transaction is expected to close in the second half of calendar year 2008 and to more than double HP's services revenue, which amounted to \$16.6 billion in fiscal 2007. The companies' collective services businesses, as of the end of each company's 2007 fiscal year, had annual revenues of more than \$38 billion and 210,000 employees, doing business in more than 80 countries.

HP intends to establish a new business group, to be branded EDS - an HP company, which will be headquartered at EDS's existing executive offices in Plano, Texas. HP plans that EDS will continue to be led after the deal closes by EDS Chairman, President and Chief Executive Officer Ronald A. Rittenmeyer, who will join HP's executive council and report to Mark Hurd, HP's chairman and chief executive officer.

HP anticipates that the transaction will be accretive to fiscal 2009 non-GAAP earnings and accretive to 2010 GAAP earnings. Significant synergies are expected as a result of the combination.

"The combination of HP and EDS will create a leading force in global IT services," said Hurd.

"Together, we will be a stronger business partner, delivering customers the broadest, most competitive portfolio of products and services in the industry. This reinforces our commitment to help customers manage and transform their technology to achieve better results."

Rittenmeyer said, "First and foremost, this is a great transaction for our stockholders, providing tremendous value in the form of a significant premium to our stock price. It's also beneficial to our customers, as the combination of our two global companies and the collective skills of our employees will drive innovation and enhance value for them in a wide range of industries. In addition, our Agility Alliance will be significantly strengthened."

Acquiring [EDS](#) advances HP's stated objective of strengthening its services business. The specific service offerings delivered by the combined companies are: IT outsourcing, including data center services, workplace services, networking services and managed security; business process outsourcing, including health claims, financial processing, CRM and HR outsourcing; applications, including development, modernization and management; consulting and integration; and technology services. The combination will provide extensive experience in offering solutions to customers in the areas of government, healthcare, manufacturing, financial services, energy, transportation, communications, and consumer industries and retail.

Under the terms of the merger agreement, EDS stockholders will receive \$25.00 for each share of EDS common stock that they hold at the closing of the merger. The acquisition is subject to customary closing conditions, including the receipt of domestic and foreign regulatory approvals and the approval of EDS's stockholders.

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Audio webcasts

This morning, HP and EDS will jointly conduct two audio webcasts, one with investors and the other with media, to discuss HP's agreement to acquire EDS.

Audio webcast for financial analysts and stockholders: 8 a.m. ET / 5 a.m. PT, hosted by Hurd and Rittenmeyer, at www.hp.com/investor/hpedswebcast.

Audio webcast for media: 9 a.m. ET / 6 a.m. PT, hosted by Hurd and Rittenmeyer, at <http://www.hp.com/go/HPtoacquireEDS>.

Additional information and where to find it

EDS intends to file with the Securities and Exchange Commission a preliminary proxy statement and a definitive proxy statement and other relevant materials in connection with the merger. The definitive proxy statement will be sent or given to the stockholders of EDS. Before making any voting or investment decision with respect to the merger, investors and stockholders of EDS are urged to read the proxy statement and the other relevant materials when they become available because they will contain important information about the merger. The proxy statement and other relevant materials (when they become available), and any other documents filed by EDS with the SEC, may be obtained free of charge at the SEC's website at <http://www.sec.gov>. In addition, investors and stockholders may obtain free copies of the documents filed with the SEC by going to EDS's Investor Relations page on its corporate website at <http://www.eds.com> or by directing a request to EDS at 5400 Legacy Drive, Plano, TX 75024 -- Attention: Investor Relations.

Participants in the solicitation

EDS and HP and their respective directors and executive officers may be deemed to be participants in the solicitation of proxies from EDS stockholders in connection with the merger. Information about HP's directors and executive officers is set forth in HP's proxy statement on Schedule 14A filed with the SEC on January 29, 2008 and HP's Annual Report on Form 10-K filed on December 18, 2007. Information about EDS's directors and executive officers is set forth in EDS's proxy statement on Schedule 14A filed with the SEC on March 4, 2008 and EDS's Annual Report on Form 10-K filed on February 27, 2008. Additional information regarding the interests of participants in the solicitation of proxies in connection with the merger will be included in the proxy statement that EDS intends to file with the SEC.

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Acquisitions

Mentor Graphics Acquires Assets of Ponte Solutions—Technology to be Integrated into Calibre DFM Solutions

15 May 2008

Mentor Graphics Corporation announced it has acquired the assets of Ponte Solutions, Inc., the Mountain View, CA developer of model-based design for manufacturing (DFM) solutions that analyze, predict, and reduce the impact of process variability during the manufacture and design of semiconductors. Terms of the transaction were not disclosed.

“We are pleased to have the Ponte team joining Mentor Graphics’ design-to-silicon business unit where they will contribute to future generations of Mentor solutions,” said Joseph Sawicki, vice president and

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general manager for the design-to-silicon division at Mentor Graphics. “DFM issues continue to be more complex as we move to 32 and 22 nm process nodes. Having access to multiple integrated DFM capabilities delivered on the Calibre® platform via Mentor’s worldwide direct sales and support channels is a clear advantage for design teams as they encounter these new DFM challenges.”

“Ponte shares Mentor’s vision for an integrated DFM offering being required as the semiconductor market continues to evolve,” said Alex Alexanian, president and CEO, Ponte Solutions. “While Ponte was providing a solution for today’s requirements, it makes complete sense for Ponte to align with Mentor Graphics to deliver complete DFM technology on the market-leading Calibre® platform going forward.”

Ponte personnel and technology will be merged into the respective departments within the Mentor Graphics Calibre organization under Joe Sawicki. Mentor will maintain the Ponte R&D team located in Yerevan, Armenia, a center of excellence for electronic design automation (EDA) and other technical software companies in Eastern Europe including Microsoft, Virage Logic, Synopsys and Credence Systems. Existing Ponte products and customers will continue to be supported by Mentor Graphics as Ponte capabilities are fully integrated into the Calibre DFM platform.

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Synopsys Completes Acquisition of Synplicity, Inc.

16 May 2008

Synopsys, Inc. announced it has completed its acquisition of Synplicity®, Inc. The acquisition expands Synopsys' technology portfolio, channel reach and total addressable market by adding complementary products and expertise for FPGA solutions and rapid ASIC prototyping. Synopsys acquired Synplicity for \$8 cash per share, resulting in a gross transaction of approximately \$223 million, or approximately \$181 million net of cash acquired.

As a result of the acquisition, Synopsys has formed a Synplicity Business Group with Synplicity President and Chief Executive Officer Gary Meyers as its general manager. Synplicity Co-Founder and CTO Ken McElvain has joined the group to help architect Synopsys' system level solutions.

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Synplicity Announces Shareholder Approval of Agreement of Merger With Synopsys, Inc.

15 May 2008

Synplicity, Inc. announced that its shareholders, voting at a special meeting today at Synplicity’s headquarters in Sunnyvale, California, have voted to adopt and approve a merger agreement pursuant to which Synplicity will be merged with and into a wholly owned subsidiary of Synopsys, Inc. More than 76 percent of the Synplicity common stock outstanding on the record date were cast in favor of adoption and approval of the merger agreement.

On March 20, 2008, [Synplicity](#) and Synopsys announced the signing of the merger agreement under which Synopsys will acquire Synplicity. Adoption and approval of the merger agreement by Synplicity’s shareholders satisfies one of the conditions to completion of the transaction. Subject to the satisfaction of the remaining closing conditions, the merger is currently expected to be completed on or about May 15, 2008. Upon completion of the merger, Synplicity common stock will cease trading on NASDAQ.

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CIMdata News

CIMdata Opinion Poll: Most Important Criteria in Your Company's PLM Evaluation and Selection Process

16 May 2008

There are only TEN business days left to vote in our current opinion poll: Which was the most important criteria in your company's PLM evaluation and selection process? Voting will close at noon on May 30. Please take a moment to [vote](#) right now.

The results of these polls are tabulated as you vote. The results are completely anonymous.

If you have a suggestion for a poll you'd like to see contact us at info@cimdata.com.

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Company News

Anark Announces Sale of Entertainment Division and Series 4 Expansion Financing

13 May 2008

Anark Corporation announced that it has sold its Entertainment Software Division, including its Gameface UI software platform. It also completed an additional funding transaction that will allow it to focus entirely on its growing Enterprise 3D CAD-PLM and Visualization division.

Anark's Entertainment Division has delivered 3D tools and middleware platforms to leading video game and entertainment content developers since 2002. Anark's products helped streamline interactive 3D content creation and deployment for many industry leading customers, such as Microsoft, Sony, and Nvidia.

In mid-2007, Anark launched the Anark Core Platform, targeted at the enterprise CAD-PLM market. This software platform reduces repetitive CAD file conversion and preparation tasks, enabling efficient and secure interoperability between producers and consumers of 3D CAD data for applications such as OEM-Supplier data exchange, technical illustration, and visual-simulation.

The current platform, Anark Core version 1.1, provides users with design-feature removal capabilities (parts, holes, fillets), then exports modified CAD data into high-precision BREP and lightweight mesh file formats including CATIA V4/V5, Parasolid, Pro/E, STEP, NX (formerly Unigraphics), IGES, Collada, DWF, X3D, and VRML. All of these steps can be automated in process-driven workflows specific to each project underway.

“Anark's history working with leading manufacturers such as Boeing, Cessna, Lockheed Martin, and Pratt & Whitney has given us considerable experience overcoming major obstacles that prevent the effective use of 3D product data throughout the enterprise and supply chain,” said Stephen Collins, President and CEO of Anark Corporation. “The Anark Core Platform has been well received by our customers, reducing the time and effort of preparing 3D CAD files for data exchange, collaboration, and visual-simulation applications by as much as 80 percent compared with competing products and

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solutions.”

[Anark](#) is already ramping up its product development efforts, with the goal of delivering Anark Core Version 2.0 in the coming months, as well as continuing to evolve and expand the capabilities of the Anark Media Platform. The company is also expanding its Sales Operations across North America, Europe, and Asia.

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BE Careers Network and The CAD Academy Team to Offer Students Bentley Civil Engineering Software

14 May 2008

Bentley’s BE Careers Network and The [CAD Academy](#) have teamed to provide students easy, affordable access to Bentley PowerCivil, comprehensive 2D/3D drafting and design software for land development and site modeling professionals. The CAD Academy is a collaboration of professionals, industry leaders, and educators dedicated to creating comprehensive pre-engineering and pre-architecture programs for the education community. The organization bundles CAD software with class curricula to help K-12 and community college students explore technology-related career paths through real-world projects. Through a new joint program with Bentley, The CAD Academy will be able to provide secondary schools and community colleges with the ability to train students in Bentley integrated software applications used by civil engineers and designers for site modeling, survey, drainage, water and sewer, road, earthworks, and subdivisions.

Alan Cox, vice president of The CAD Academy, said, “Through innovative and forward-thinking companies like Bentley, The CAD Academy is able to expose students to the latest technology available and, thus, encourage them in their pursuit of a career in engineering. Bentley PowerCivil is a great addition to our technology offerings and opens the door to yet another engineering discipline for students to investigate.”

BE Careers Network is dedicated to helping students graduate with market-ready technology skills. It accomplishes this by providing programs for students, teachers, and schools, including free and discounted software licenses, training, curriculum counseling, and scholarships. The programs are geared to the needs of students in middle schools, high schools, technical schools, colleges, and universities.

Commenting on the new joint program with The CAD Academy, Scott Lofgren, global director of BE Careers Network, said, “BE Careers Network welcomes the opportunity to establish relationships with premier educational programs like The CAD Academy. It’s one of the many ways in which we help empower schools to integrate the teaching of infrastructure concepts and infrastructure software. Our ultimate goal is to increase the number of graduates in infrastructure professions while also making sure they have excellent software skills and are productive with commercial software their first day on the job.”

To get more details on BE Careers Network, visit <http://www.becareers.org>.

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Centric Names Industry Veteran Dave Guercio to Top Sales and Services Role

13 May 2008

[Centric Software](#) announced that David Guercio has joined the company as executive vice president of sales and client services. In this pivotal role, Guercio will lead Centric's worldwide efforts to grow its sales and professional services organizations to meet the company's growth objectives and deliver PLM solutions to customers in the apparel-footwear-accessories and private label industries.

Guercio brings nearly 30 years of technology and software industry experience to his role at Centric. He has a demonstrated track record of successful team building, and helping emerging companies navigate transitions as they expand operations and global reach. Most recently, Guercio was senior vice president of sales and marketing at Inxight Software, a leading provider of software solutions for unstructured information discovery. During his tenure, Guercio grew the sales and professional services teams and revenue to position Inxight to be acquired by Business Objects.

Prior to his role at Inxight, Guercio held executive operational positions at Resonate, Neovista, Metaphor Computer Systems, and other firms. In each of these roles, Guercio was able to build successful sales and services teams, increase customer satisfaction and help companies grow to "the next level."

"We are completely focused on our plan to assure that Centric is a force to be reckoned with and the leading PLM solution provider for fast moving consumer goods industries," said Chris Groves, president and CEO of Centric Software. "The addition of Dave's experience in helping companies grow and successfully build their sales and services teams is critical to that plan."

"We've taken important steps in other areas as well," added Groves. "These include the placement of our Series B funding, the addition of Ray Hein as executive vice president of market strategy and business development, and important additional hires throughout the organization to continue to build domain expertise in our target markets. Dave's contributions will be a critical factor for our success during this dynamic time at Centric, and we welcome him."

"Centric presents an exciting and rare opportunity," said Guercio. "Its people, technologies, and funding position it to succeed in the apparel-footwear-accessories and private label industries. My first areas of focus will be helping our sales and services teams grow and making sure they have the tools and processes to become world-class organizations. I'm delighted to be part of the team that will take Centric to the next step in its growth as an enterprise."

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Collaborative Multi-Company, Multi-Disciplinary Jet Engine Design

13 May 2008

This article highlights a concept developed to address the needs for a multi-enterprise collaborative design system. During the 4-year EU Framework 6 VIVACE project, a virtual enterprise collaborative framework called VEC-Hub was developed based on Eurostep's server solution Share-A-Space, and Engineous' FIPER solution. It allows flexible addition or modification of partners and/or accommodation of tool suites. The approach demonstrates efficient support of evolving engine design for a realistic design problem in a realistic organizational setting, thereby alluding to its potential in similar high-tech design collaborations.

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The feature article "Collaborative Multi-Company, Multi-Disciplinary Jet Engine Design Process" was published in NAFEMS BENCHmark Magazine, April 2008, Simulation Driven Design Issue. Please download the [article](#).

If you are interested in more information about Eurostep's participation in the Vivace project or the usage of Share-A-space in the VEC-Hub solution, please contact [Väino Tarandi](#), or visit the [website](#).

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Dassault Systèmes Opens Chengdu Office, Expanding Operations in China

12 May 2008

Dassault Systèmes announced the opening of its fourth office in China, at Chengdu, Sichuan. The Chengdu office will serve as the hub for Dassault Systèmes' sales operations in Southwest China. In China, the company has three other offices – Beijing, Shanghai and Guangzhou.

“The opening of our fourth office in China brings us closer to our customers in the Southwest region,” explains Mr. Zhao Heng, Vice President, Greater China Value Channel, Dassault Systèmes. “Through our Chengdu office, we can provide dedicated technical and customer support to many of our important customers in this region. The region is set to be the fastest growing in Greater China, and we need to be present to assist our existing and future client base, in line with our aggressive growth plans.”

Chengdu, one of the most important economic, transportation and communication hubs in China will serve as a spring board for Dassault Systèmes expansion in mainland China. By being closer to its customers in the region, the company aims to expand its existing customer base in markets in which it is already a leader, including aviation, energy, automotive and education.

“Chengdu being the economic hub of Southwest China, it is important that any company that is committed to China has a presence here,” said Mr. Zhao Heng, Vice President, Greater China Value Channel, Dassault Systèmes. “Our presence in Chengdu is inline with the Chinese government’s “Go West” policy, so that we can contribute actively to the economic and social development of this thriving region.”

The Chengdu office represents Dassault Systèmes' latest expansion and continued growth in China. In addition to strengthening its presence in key regions, the company also holds an Annual PLM Executive Summit, bringing together the most influential Chinese manufacturers to share and exchange ideas on how Dassault Systèmes' PLM solutions can help local enterprises to keep pace and innovate for growth. Some of Dassault Systèmes' Chinese customers include Chengdu Aircraft Industrial Group, Chengdu Hydropower Investigation Design & Research Institute - CHECC, Yan Tai Raffles Shipyard and SAIC MOTOR CORPORATION LIMITED. The company's solutions are also being used to prepare for the upcoming Beijing Olympics, including the design of the National Beijing Stadium and other sports facilities.

For more information please visit <http://www.3ds.com/cn>.

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Liberty Technical Advisory Board Expands Under the Auspices of IEEE Industry Standards and Technology Organization

14 May 2008

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[Synopsys, Inc.](#) announced that the Liberty™ Technical Advisory Board (TAB) is expanding under the auspices of the IEEE Industry Standards and Technology Organization (IEEE-ISTO). After a successful incubation period under the Silicon Integration Initiative (Si2), the move to [IEEE-ISTO](#) enables the expansion of Liberty TAB membership to include more participants from the semiconductor and electronic design automation (EDA) industries. Newly added member companies include Magma Design Automation and Mentor Graphics. The Liberty TAB and its industry-leading member companies will continue to guide the evolution of the Liberty standard for library modeling, with a focus on improved productivity and reducing costs in creating and producing integrated silicon systems.

"Si2 has done an excellent job facilitating the launch of the Liberty Technical Advisory Board and gaining participation from the 12 founding member companies representing various facets of the semiconductor industry," said John Chilton, senior vice president of Marketing and Strategic Development at Synopsys. "The endeavors of all the Liberty TAB members under Si2's auspices have enabled the Liberty format to broaden in its scope and value to the design community. We thank Si2 and its president, Steve Schulz, for all their efforts to help accelerate innovation in the industry and drive the Liberty standard to the next level."

"One of Si2's key objectives is to engage and support EDA industry collaborative initiatives," said Steve Schulz, president and CEO of the Silicon Integration Initiative.

"We are pleased to have been part of this innovative chapter in the evolution of the Liberty standard. We believe the expansion of the Liberty TAB will foster further EDA industry collaboration and we wish its members continued success under the new organization."

"Magma continually works to provide designers with open, highly interoperable flows that enable them to address the power, variability, manufacturability, yield and time-to-market challenges of 45-nanometer designs," said Kam Kittrell, general manager of Magma Design's Implementation Business Unit. "By participating in the Liberty TAB, we can help guide the evolution of the Liberty standard to better address the requirements of the semiconductor industry."

"As our customers move to smaller geometries, the industry needs to align its efforts to evolve the Liberty standard," said Joseph Sawicki, vice president and general manager of the Design-to-Silicon Division at Mentor Graphics. "The Liberty Technical Advisory Board is the right place to do it, and we welcome the broad inclusiveness under IEEE-ISTO."

Under IEEE-ISTO, the Liberty TAB will grow, over time, from 12 to approximately 20 members. Member companies represent the broad semiconductor industry including the design community, EDA companies, silicon foundries, and semiconductor intellectual property (IP) companies. Requests for enhancements can come from the membership as well as from the overall Liberty user base. Companies interested in membership in the Liberty TAB may contact IEEE-ISTO.

The latest Liberty syntax specifications and tools can be found at <http://www.opensourceliberty.org/>. Open Source Liberty is a comprehensive online resource for the Liberty library modeling standard. In addition to providing up-to-date Liberty format specifications and related tools for download, this site hosts the Liberty Discussion Forum, where members of the semiconductor community can interact with each other and discuss topics relating to the Liberty format and the Composite Current Source (CCS) modeling technology. This site also provides the latest news and information regarding the Liberty format and the Liberty TAB.

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CIMdata PLM Industry Summary

Mentor Graphics Offers Personalized Web Support Portals; First to Earn Certification under the SCP eService Standard

13 May 2008

Mentor Graphics Corporation announced it has re-architected SupportNet, <http://supportnet.mentor.com/>, its web customer support site, offering users an individually customizable portal for easy access to technical product information of interest to them. The company is also the first company to earn certification for its web support services through the internationally recognized Service Capability & Performance (SCP) Standards. Mentor earned certification under the SCP eService Standard after an extensive audit of its global online customer support operations.

“Mentor has hundreds of products and thousands of application notes, how-to videos, product updates and the like on SupportNet. By offering customers a way to customize SupportNet to the products they care about, we’ve reached a rather remarkable 76% success rate for on-line support,” said Tom Floodeen, vice president of customer support for Mentor Graphics. “Not only does this offer customers a powerful and swift way to get the answers they need, but when customers can find what they want quickly on-line, it allows us to focus on more complex problems, speeding responses there, too.”

With hundreds of products, electronic design automation (EDA) customers can struggle to find the information relevant to their needs. The new SupportNet allows customers to select the products that they care about and filter out extraneous information. The company studied customer usage patterns and developed statistical information to better prioritize content display for the most critical and common tasks customers wanted to do. The portals are further segmented based on customer role, either designer or system administrator. SupportNet is architected to enable continuous customer usage analysis to further refine information display, so evolving usage needs can be met.

SupportNet provides full on-line searchable documentation, as well as natural language query supported by InQuira. Searching across thousands of pages of content including PDFs can be troublesome for any search technology. Customer feedback helped Mentor determine that the biggest factors for successful searches were a) the ability to enter an entire phrase or question and b) pinpointing the exact match whether in HTML or PDF content.

The SCP Standards are designed to improve the quality and effectiveness of support. A consortium of leading technology companies, along with Service Strategies Corporation, created the internationally recognized standards, which define best practices, quantify performance levels, and establish a foundation to continuously improve service operations. Achieving certification against SCP Standards requires annual comprehensive audits to confirm that companies meet the requirements defined by the program. Launched in 2007, the SCP eService Standard measures approximately 50 eservice factors including usability and design, security and privacy, and self help services.

The new SupportNet customized portals are available today to all users of Mentor Graphics Support at no additional charge at <http://supportnet.mentor.com/>.

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Siemens PLM Software: Key Milestones Achieved During its First Year

13 May 2008

[Siemens PLM Software](#) celebrated a series of milestones achieved during its first year as part of Siemens AG. “In the one year since Siemens AG announced the close of its acquisition of UGS, we

CIMdata PLM Industry Summary

have successfully integrated our operations into those of Siemens while concurrently growing our business and capturing market share in the PLM industry,” said Tony Affuso, chairman and CEO of Siemens PLM Software. “It’s been a strong first year for us as part of Siemens, and we look forward to a long and successful future as a member of the Siemens family.”

“In addition, we moved forward with our Unified Product and Production Initiative, which we believe will fundamentally alter the landscape of what companies can expect from industry software by providing them with greater speed and confidence in bringing products to market than they have ever experienced,” said Dr. Helmuth Ludwig, president, Siemens PLM Software. “And more recently at Hanover Fair, we launched our new synchronous technology thanks to Siemens’ ability to accelerate this breakthrough technology to market. Siemens and UGS are a great combination and are off to a fast start.”

“Congratulations to Siemens PLM Software for a fantastic year – we are so pleased to have the team as part of the Siemens family. Our shared vision of unifying the product and production lifecycles is becoming a reality,” said Peter Loescher, president and CEO, Siemens AG during a site visit at the Siemens PLM Software location in Detroit.

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Synopsys Donates Proven VMM Methodology Library and Applications to Accellera

12 May 2008

Synopsys, Inc. announced that it is donating its complete implementation of the proven VMM verification methodology for SystemVerilog, including the VMM Standard Library and VMM Applications, to Accellera to enable verification interoperability standardization. Accellera has accepted the donation so the recently formed Accellera Verification IP (VIP) Technical Subcommittee can use it for their standardization activities.

The VMM methodology, originally defined in the Verification Methodology Manual for SystemVerilog, has been used successfully by hundreds of verification teams since its introduction in 2005. Synopsys' donation to Accellera addresses customers' demand for a modular, scalable and reusable design methodology standard while enabling them to more easily develop and share complex verification environments.

"Accellera's newest standardization activity will promote interoperability among vendors' and users' verification methodologies," said Shrenik Mehta, Accellera chair. "The donation of Synopsys' VMM implementation provides the technical subcommittee with established technology to meet their objectives."

"The enormous investment in the VMM methodology made by Synopsys, its partners and customers over the past four years has helped design teams around the world take full advantage of SystemVerilog," said Manoj Gandhi, senior vice president and general manager of the Verification Group at Synopsys. "Accellera's acceptance of Synopsys' donation of its complete implementation of the VMM methodology enables Accellera to leverage this investment to create a single, unified standard that will accelerate the pace of innovation."

Complete VMM Methodology

A complete methodology requires more than just a standard base class library. It requires applications that provide high-level functions to further increase productivity, macros and utilities to cut down

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testbench creation time, and clear documentation and examples to shorten the learning curve. Synopsys has donated its complete implementation of the VMM methodology, which includes:

- * VMM Standard Library
- * VMM Register Abstraction Layer application
- * VMM Reusable Environment Composition application
- * VMM Memory Allocation Manager application
- * VMM Hardware Abstraction Layer application
- * VMM Data Stream Scoreboard application
- * VMM Macro Library

Chip development teams need to have confidence that their verification methodology is mature, full-featured and scalable. One of the best ways to gain this confidence is to look for other teams who have used a methodology successfully on multiple projects. The VMM methodology has been successfully deployed by hundreds of project teams across the globe since 2005, and over 50 technical papers and tutorials on the VMM methodology have been presented at Synopsys User's Group (SNUG) meetings and other venues.

Broad Vendor Support

By way of the VMM Catalyst program, EDA suppliers throughout the industry are able to leverage VMM technology and expertise to create tools, verification IP (VIP), training, and services for chip development teams. More than thirty companies are currently members of the VMM Catalyst program.

VMM User Forum

Synopsys will be sponsoring a VMM luncheon at the Design Automation Conference (DAC) in Anaheim, Calif. on June 10, 2008. Join Synopsys and VMM users to explore how VMM has extended methodology beyond base classes. For more information and to register, please visit <http://www.synopsys.com/dacvmm/> VMM will also be featured in Synopsys' main booth at DAC (booth # 1349) and in the Synopsys Standards Booth at DAC (booth # 1541).

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Events News

Announcing IP Talks! 2008: Meet With Leading IP Suppliers at DAC

13 May 2008

Semiconductor IP will take center stage at IP Talks! 2008, a showcase for the latest IP technology at this year's Design Automation Conference (DAC). Sponsored by the ChipEstimate.com chip-planning portal, IP Talks! provides an opportunity for DAC attendees to meet with leading IP suppliers and learn about how the latest in semiconductor IP can help them accelerate their design success. Now in its second year, IP Talks! can be seen June 9-11 at booth 2358.

This year's IP Talks! will include live presentations from Algotronix, ARM, Cadence, The Common Platform, Denali, Elliptic, eSilicon, IPextreme, GSA, Kilopass, Mixel, Mosys, Rambus, Sarnoff Europe, Silicon & Software Systems (S3 Group), Sidense, Synopsys, True Circuits and Virage Logic. A

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schedule of presenters — which is being updated often — is available at <http://www.chipestimate.com/dac2008/>.

The ChipEstimate.com chip-planning portal hosts a collaborative partnership of over 175 IP suppliers and foundries featuring over 6,000 IP components. This partnership enables customers to access a wide range of design and verification IP and to explore and quantify the IP within their specific design context. IP quality and technical characteristics are accessible to assist design teams in performing what-if analysis and driving the IP exploration process.

"IP Talks! is a fantastic service for semiconductor designers," said Lisa Tafoya, vice president of Global Research for the Global Semiconductor Alliance (GSA). "It provides a unique opportunity to learn and ask questions about developments in IP that can help ensure the IP industry meets the ambitious quality and time-to-market demands of the semiconductor community."

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Autodesk Showcases Design Innovation Technologies

15 May 2008

[Autodesk, Inc.](#) is highlighting its portfolio of software solutions for the architecture, engineering and construction (AEC) industries and demonstrating new technologies for design innovation in practice at the 2008 AIA National Convention and Design Expo, booth 20121, which is made entirely from sustainable materials.

As AEC industry firms continue to adopt building information modeling (BIM) in search of competitive advantage and to improve productivity and efficiency, Autodesk is demonstrating discipline-specific software solutions for BIM that support building design, engineering, construction, fabrication and operation. The official software sponsor of AIA150, Autodesk is also showcasing how high-quality, reliable and coordinated information created in the BIM process can be used for conceptual design, sustainable design and design visualization and is demonstrating its new Autodesk Seek web service and product content search. Autodesk also announced that it has sold more than 300,000 seats of its Revit software platform for BIM, representing a 200% increase in seats over the past two years.

"The rapid move to BIM has created a foundation for change in the AEC industry," said Jay Bhatt, senior vice president, Autodesk AEC Solutions. "Autodesk is investing aggressively in new applications and technology solutions that build on the promise of BIM and support our customers' need to create, predict and deliver their ideas in increasingly more optimal and effective ways."

Robert Aish to Lead Development of Conceptual Design Tools

Dr. Robert Aish, an AEC industry thought leader and software originator, has recently joined Autodesk to lead the company's development of conceptual design solutions to help architects and designers more easily create and analyze complex forms earlier in the design process. Dr. Aish is graduate of the School of Industrial Design at the Royal College of Art, London and holds a Ph.D. in Human Computer Interaction from the Man-Machine Lab at the University of Essex. More recently, Dr. Aish co-founded the SmartGeometry educational initiative which has established parametric and computational design as an essential component of creative architecture.

"Autodesk is an industry leader with a long history of creating innovative design software," said Dr. Robert Aish, Director of Software Development, Autodesk AEC Solutions. "Through the development of new conceptual design solutions for early design exploration and analysis, I believe we can improve

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and streamline the creative process for millions of architects and designers around the world"

At the AIA Expo, Autodesk will demonstrate how products from its technology portfolio including Maya and Inventor are being used by innovative AEC industry firms for conceptual design. Maya, a complement to the BIM process during conceptualization, is an integrated 3D modeling, animation and visual effects solution that enables architects and designers to freely create and manipulate complex organic shapes. Inventor enables the use of rules-based modeling for architects and designers who look to parametrically drive form to explore, iterate, and rationalize conceptual designs. The software also provides a comprehensive and integrated set of design tools for producing, maintaining and documenting complete digital prototypes and enables users to validate the form, fit and function of a design before it is physically built.

New Analysis Technology for Sustainable Design

As the AEC industry expands its adoption of BIM and sustainable design practices, Autodesk has continued to develop and acquire technology to help architects and engineers design better performing projects by leveraging the data created in the Revit platform for BIM. The recent acquisitions of building performance and sustainable analysis tools, including technology developed by Green Building Studio, Intelisolve, and Carmel Software, are part of Autodesk's efforts to drive mainstream adoption of sustainable design. At the 2008 AIA Expo, Autodesk is demonstrating how these analysis tools can be used as part of the BIM process, and how through BIM, the information required for sustainable design, analysis, code compliance, and certification can become routinely available as a by-product of the standard design process, helping to save time and money.

3ds Max Design and Revit Architecture Provide Enhanced Visualization Capabilities

Autodesk will demonstrate the new Autodesk 3ds Max Design software -- a 3D visualization solution that allows AEC professionals to explore, validate and communicate their ideas. Revit Architecture 2009 will also be demonstrated, featuring a new implementation of the mental ray rendering engine, which improves the speed, quality and usability of rendering and visualization features in BIM. For designers who require more visual control, animation capabilities and rendering power, Revit Architecture 2009 provides a new bridge to 3ds Max Design. This enables users to deliver richer visuals and more precise information from the underlying building model. Complementing Revit Architecture, 3ds Max Design provides the Exposure daylight simulation and analysis system, which assists architects in evaluating light intensity against indoor environmental lighting quality requirements, such as LEED EQ Credit 8.1.

Autodesk Seek Provides Building Product Information to Architects and Designers

Extending the scope of the Revit platform for BIM and AutoCAD Architecture 2009, the newly released Autodesk Seek delivers quick results from an online source for building product information, including 3D models and product specification data. This new search tool, accessible from inside AutoCAD and Revit-based applications, or via a browser, will also be on display. Negating the process of browsing product specification catalogues, this combination of software and service allows designers to search, select and specify products, seamlessly, in their design workflow.



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Cimatron to Exhibit Advanced Machining Techniques and Newly Released CAD/CAM Capabilities at EASTEC

15 May 2008

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Cimatron's suite of integrated CAD/CAM solutions will be on display at the upcoming EASTEC tradeshow (May 20 – 22, 2008, West Springfield, MA).

Cimatron's CAD/CAM solutions are proven to help tool makers deliver higher quality tools at lower costs and shorter cycle times—addressing the entire process from quoting through design, engineering changes, NC, and EDM programming to delivery. Visitors to the show will be able to see Cimatron's advanced machining techniques, as well as recently released CAD/CAM enhancements.

Advanced Machining

Cimatron facilitates the machining of any part – from simple 2.5 axis milling and drilling to complex 5-axis machining - including micro and aerospace milling. The rich CAD functionality built into the NC environment provides a highly productive work environment that produces superior surface quality. The integrated end-to-end solution eliminates the need for error-prone and time consuming data translations and enables quick response to engineering changes.

These machining solutions and more will be demonstrated at Cimatron's booth #5740 at EASTEC 2008.

“In today's highly competitive market, tool makers and manufacturers can no longer afford to use outdated technology. We are excited to share with EASTEC attendees technologies that can help them improve quality and shorten delivery times”, said Bill Gibbs, CEO and President, Cimatron Technologies, Inc.

Also on display at the show will be new capabilities recently released in CimatronE version 8.5. These include modified NC reports, enhancements to the Automated Drill application, spiral cut milling and 3-5 Axis transformations in 5-Axis Production, expanded concurrent engineering capabilities, integrated CADENAS catalogs and “blank on binder” (for die makers).

Streamlined Numerical Control

Modified NC Setup Reports: Automatically-generated NC reports facilitate the information flow between NC programmers and the shop floor, providing machine operators with detailed information that includes the tool paths, procedures, tools, and parameters for each job. Images and user-specific information can be added to the reports, which can be presented either online or in print.

Automated Drill: New operations added to the Automated Drill application include profiling of holes and threading cycles, as well as pocketing for pre-drill preparation of difficult to drill areas such as slanted surfaces. These operations can be integrated into the automated drill sequence and reused from libraries to increase efficiency and accuracy.

5-Axis Production: CimatronE version 8.5 features new enhancements to the 5-Axis Production application, including spiral cut milling, 3-5 Axis transformations, and advances in impeller roughing.

Concurrent Engineering

Cimatron's concurrent engineering capabilities improve productivity and collaboration and significantly compress product delivery times.

Concurrent design capabilities are built into Cimatron's CAD applications, enabling multiple users to simultaneously work on the same assembly and shorten the design cycle. Starting with the new release of CimatronE version 8.5, these concurrent design capabilities are available throughout the entire CAD product line.

Cimatron's support for concurrent engineering extends beyond the design phase. The integrated end-to-

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end design-to-manufacturing solution uses a single database that provides complete associatively and enables multiple steps of the design and manufacturing process to be performed in parallel.

Integrated CADENAS Catalogs

CADENAS PARTsolutions is now integrated into CimatronE 8.5, enabling tool makers to shorten design cycles by incorporating ready-made CADENAS catalog parts into Cimatron tool assemblies.

While the catalog functionality has long been available in Cimatron's software, the CADENAS catalogs place thousands of new standard components at the disposal of Cimatron users, eliminating many of the manual and time-consuming steps in the tool design process.

"Blank on Binder" for Die Makers

Creating intermediate binder blanking surfaces and unfolding the part on these faces is one of the most challenging tasks in the die design process. In most cases, accurate results can only be achieved after a laborious and expensive trial and error process.

Based on a finite element analysis, CimatronE's "Blank on Binder" enables the user to perform this task and unfold freeform shapes onto a 3D geometry with unprecedented speed and accuracy.

Visit [Cimatron](#) at EASTEC, May 20 - 22, 2008

Eastern States Exposition

Booth #5740

See also the latest innovations for Production by visiting the GibbsCAM booth #5429.

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CIMdata's Ed Miller Is Keynote Speaker at PLM World, June 4, 2008 on the Challenges Presented by the Expanding Scope of PLM

Who: Ed Miller, President of CIMdata

When: Wednesday June 4 8:30 a.m.

Where: PLM World June 2-5, 2008 Orlando Florida

Topic: The Expanding Scope of PLM – A Growing Challenge

The scope of Product Lifecycle Management (PLM) has been continuously expanding to more effectively support the full digital product lifecycle. This expansion has created additional stress and corresponding opportunities for industrial companies seeking to establish a strategy and develop tactical plans to accommodate this expanded perspective. A particular challenging issue is to understand the relative positions of PLM and other enterprise-wide initiatives. While this has traditionally involved PLM and ERP positioning, we have also seen the inclusion of aspects traditionally considered components of MRO and SRM into PLM. We are seeing the PLM domain continually expand. More recently it has become critical to also consider the overlap and integration with the shop floor and associated Execution systems. This expansion is expected to continue. CIMdata sees the role of key enterprise processes playing a major role in deciding the boundaries between these initiatives in the future. Mr. Miller will discuss this evolving situation and CIMdata's perspective on the overlaps and interactions of these of major product-focused IT-enabled enterprise initiatives.

Link: http://event.plmworld.org/schedule/keynote_presentations.php

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Delcam to Launch New PowerMILL at IMTS

15 May 2008

The next release of Delcam's PowerMILL CAM software will be launched at the IMTS exhibition to be held in Chicago from 8th to 13th September. The new version will offer a more complete solution for complex machining operations, together with more control for experienced machinists that know exactly how they wish to machine a particular part. The program will also include a range of enhancements to existing functionality to enable both faster programming and faster machining.

"Ever since its first release, PowerMILL has focussed on the more complex parts of any manufacturing operation," explained Delcam's CAM Development Director Steve Hobbs. "Many of our toolmaking customers tend to program the simpler tasks, like sizing the starting block of material, and finishing operations, such as cutting off, on the machine tool control rather than by off-line programming. However, as we have become more established in production machining, a growing number of our customers want to program everything with their CAM system. This has always been possible in PowerMILL but the new options in PowerMILL 9 will make the complete programming process much easier."

Using a completely offline approach to programming gives other benefits as well. Firstly, it ensures that a fully-detailed record is maintained of the whole manufacturing process. This will make it easier for jobs to be repeated by different staff, or even at different locations, and will ensure a consistent approach is maintained whenever and wherever a part is produced subsequently.

Secondly, it makes simulation of the complete process easier and more reliable. The simulation can begin from the starting block of material, rather than the user having to produce a model of the stock remaining after the manually-programmed operations have been completed.

More machining control

Much recent development in PowerMILL has focussed on making it easier for inexperienced and casual users to generate high-quality toolpaths for high-speed and five-axis machines tools. However, very experienced users tend to know exactly how they want to manufacture a particular part, or undertake a particular operation. They need greater control over the results that their software can give to achieve maximum productivity, even if this requires more skill and experience with the program.

PowerMILL 9 gives them this control by making it easier for experienced users to generate toolpaths based on any 3D curve. This was possible previously using PowerMILL's pattern machining commands but the new approach makes it easier both to create the required 3D curve and to drive the cutter along it.

Faster programming and machining

PowerMILL 9 includes a range of enhancements to give faster programming and faster machining.

"Originally, many customers would buy PowerMILL simply because it was the only CAM system that could machine their components or tooling," explained Mr. Hobbs. "Now, while there are some other CAM systems that can be used to manufacture complex parts, these cannot match the speed and quality of both programming and machining that our customers can achieve with PowerMILL."

PowerMILL 9 incorporates a number of improvements to reduce calculation times, together with some

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simplification of the user interface that makes it easier to select the required command and so makes programming faster. In addition, toolpath ordering has been made more efficient, especially for roughing and rest machining, so ensuring that the cutter spends more time machining and minimal time making air moves.

"These enhancements may not grab as many headlines as completely new machining strategies," admitted Mr. Hobbs. "However, they are vital to our customers that need to increase their productivity and reduce their lead times in order to maximise their competitiveness."

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45th Design Automation Conference Panels Cover Industry's Varied Interests, Challenges, Direction, Future

13 May 2008

The 45th Design Automation Conference (DAC) will include 29 Technical Program and Pavilion panels over a four-day period, covering a variety of topics and trends related to the design of chips and embedded software.

DAC will be held June 8-13, 2008 at the Anaheim Convention Center in Anaheim, Calif. Details are available at <http://www.dac.com>.

"This year's panel line-up is especially strong and diverse," says Panel Chair Sachin Sapatnekar of the University of Minnesota. "The Panel Committee worked exceptionally hard this year to bring attendees the experts on the latest trends, the new technologies and the latest industry debates. I encourage everyone attending DAC to join the panel discussions."

Nine panels in the Technical Program, offered from Tuesday, June 10, to Thursday, June 12, will tackle the most pressing challenges, including working with multicore architectures, electronic system level (ESL) design and wireless, this year's DAC theme. Other subjects include verification, thermal, design for manufacturability (DFM) and custom design and synthesis.

One panel titled, "Electronics and Politics: What the Industry Needs from the Incoming U.S. Administration," Tuesday from 10:30 a.m. to noon, will ask participants and attendees to consider the most important initiatives for the upcoming election.

Attendees will see familiar favorites among the 20 Pavilion Panels in Booth #364 on the DAC exhibit floor. Kicking off the program Monday is "Gary Smith on EDA: Trends" and "What's Hot at DAC." The Student Design Contest Award Presentation will be held Monday as well. Another favorite — Hogan's Heroes — to be held Wednesday will attempt to answer, "Behavioral Synthesis: Is that Light at the end of the Tunnel or an Oncoming Train?" Thursday's program includes "A Conversation with the 2008 Marie R. Pistilli Woman in EDA Award Winner."

Monday Pavilion panel sessions include "EDA Heritage Series: Maxwell's Legacy" and "Next-Generation Data Centers: Environmentally Green, Financially Green." A panel of tech-savvy Java high school students will define cool in current devices and what they want in the future, in "Today's Consumers: High Schoolers Spec Your Next Product." Also to be held Monday is "Will 22 nanometer be Our Catch-22?"

Pavilion panels Tuesday are "45 nanometer: Collaborate, Aggregate, Differentiate" and "EDA: A View from Sand Hill Road." Also planned for Tuesday are "Multiprocessor SoCs: The Next Generation," "IP

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Selection: The Good, The Bad and The Ugly” and “EDA Globalization: Third World or New World?” Tuesday’s discussions continue with “Quality Versus Time to Market: The Unmentionable Tradeoff” and “SOI (silicon on insulator): Fact, Fiction or Future?”

Pavilion panel sessions Wednesday will be “Advanced Low-Power Techniques: Is Your Design Method too Powerful” and “DFM Design Rules: Worth The Effort?” “Designing the New-Generation Wireless Platform: Lesson from iPhone and Android” and “What’s Holding Back Analog Design Automation?” also are planned for Wednesday.

The Pavilion Panel Program concludes Thursday with “Your Functional Verification Roadmap: OVM, VMM or Roll Your Own?”

Visit the DAC Web site (<http://www.dac.com>) for the complete listing of panels, dates and times of each, along with a description of the topic, moderator and panelists.

This committee is headed by Panel Chair Sachin Sapatnekar of the University of Minnesota. Volunteer Panel Committee members are: Dave Reed of Blaze DFM Inc.; Andreas Kuehlmann at Cadence Design Systems Inc.; Tiffany Sparks at Chartered Semiconductor Manufacturing; Eshel Haritan of CoWare Inc.; Kevin Silver of Denali Software Inc.; Ruchir Puri from IBM; and Yatin Trivedi from Magma Design Automation Inc.

Also, Juan C. Rey from Mentor Graphics Corporation; Dave Kelf, of Sigmatix Inc.; Hiroyuki Yagi at STARC; Rich Goldman of Synopsys Inc.; Steve Leibson from Tensilica Inc.; Nagaraj NS of Texas Instruments; and Sabina Burns of Virage Logic Corporation.

Registration

To register for DAC, visit www.dac.com or call 1-800-321-4573 in the U.S. to request registration materials. The advance conference registration discount deadline is May 19, 2008.

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Geometric to Unveil DFMPPro for Pro/ENGINEER at PTC World 2008

16 May 2008

Geometric Limited announced that a new offering for Pro/ENGINEER users, ‘DFMPPro for Pro/ENGINEER’, will be showcased during the PTC User World 2008 in Long Beach, CA. Geometric will be at Booth # 301 from June 1-4, 2008.

Registration for the beta program for the product will also commence at the event. DFMPPro is a Design for Manufacturability (DFM) tool which facilitates upstream manufacturability validation and identification of design areas that are difficult, expensive or impossible to manufacture. Used at the designing stage, this tool allows quick and in-depth examination of product manufacturability and potentially, product manufacturing costs. DFMPPro performs rule based checks which can predict manufacturing problems early in the designing stage.

It reduces the design review steps, thereby pushing new products into the manufacturing stage swiftly. For more information, visit <http://www.dfmpro.com> Other products that will be showcased at the event are GeomCaliper® for Pro/ENGINEER® and eDrawings® for Pro/ENGINEER®. GeomCaliper is a wall thickness analysis tool for designers in injection molding and castings, whereas, eDrawings is a light weight visualization tool to communicate designs through email.

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GibbsCAM Featured at Mori Seiki Innovation Days

13 May 2008

Gibbs and Associates announced that GibbsCAM will be demonstrated at Mori Seiki's upcoming Innovation Days on May 14th – 16th. Innovation Days, which highlights Mori Seiki's latest CNC technology and also celebrates Mori Seiki's 25th Anniversary, is being held at Mori Seiki USA's Chicago Technical Center. Gibbs will demonstrate GibbsCAM's NC programming support of Mori Seiki's conventional and advanced multi-tasking machine tools. Gibbs will also demonstrate the latest GibbsCAM enhancement which fully supports Mori Seiki's spinning tool turning. GibbsCAM support for Mori Seiki's spinning tool operation includes rough and finish turning on any type of lathe part and the ability to control the tool axis in a variety of ways to provide an optimal tool-part cutting condition.

“Gibbs is pleased to participate at Mori Seiki's Innovation Days event and to congratulate them on their 25th anniversary,” stated Bill Gibbs, president and CEO of Gibbs and Associates. “We have worked closely with Mori Seiki to ensure that GibbsCAM supports the extensive functionality of their machine tools. Most recently, we have worked with Mori Seiki to support their spinning tool turning capability, a new approach to machining which is ideally suited for multi-tasking machine tools. We look forward to demonstrating GibbsCAM's ease-of-use in programming even the most complex Mori Seiki models.”

GibbsCAM offers comprehensive support for Mori Seiki's complete line of machine tools including verification by Mori Seiki for their NT and NMV lines of multi-task machine tools. GibbsCAM's what-you-see-is-what-you-machine post processors allow users to program in confidence with the assurance that posted output is accurate and edit-free.

For more information about GibbsCAM, or to locate your local GibbsCAM Reseller, go to <http://www.GibbsCAM.com>, call 1-800-654-9399, or email info@GibbsCAM.com. To find out more about Mori Seiki's Innovation Days or to register online, go to <http://www.moriseikius.com/id>.

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ProductDossier Participates in Two Upcoming Trade Shows

May 2008

14-17 May, 2008

ProductDossier participates (stall at HALL C) in 'Automotive Engineering Show 2008' at Auto Cluster Exhibition Centre, Chinchwad Pune on 14-17 May 2008. Sandeep Kumar, MD, will be delivering Presentation on "Automating Business Processes Using PLM" on 16 May 2008 at 5.30 PM.

30-31 May, 2008

[ProductDossier](#) participates in "IT for SME" - India's Largest event on IT adoption among SME's. The event is a combination of IT tradeshow, workshops and forums on 30 & 31st May 2008 at MCCIA Trade Towers, Pune. Sandeep Kumar - MD will be addressing the audience on 'PLM-The Growth Engine for SME's' ProductDossier has put up a stall also in the same event (Stall No A6)

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Record Number of Attendees Expected at EMC World 2008

13 May 2008

In just under one week, more than 9,000 EMC customers, partners, technologists, journalists and analysts from around the world will gather in Las Vegas for the annual EMC World user conference. EMC World (May 18-22, 2008) is a comprehensive educational forum that provides attendees with access to experts from EMC and over 100 partners, discussing and demonstrating the technologies and strategies that help customers get the maximum value from their information and their information infrastructures.

EMC World gathers a wide range of experts, partners and customers, each with a unique perspective on innovative approaches to information management across a range of industries and organizations that regard information as one of the most valuable business assets. The conference covers a multitude of the most important issues in information management today, from storage and resource management, to security, content management and virtualization.

Follow EMC World Online

Anyone can be alerted to the latest news and important event updates from attendees at EMC World 2008 by following the EMC World Twitter page at: <http://twitter.com/emcworld>

Starting May 19, EMC will also have a dedicated EMC World 2008 news page containing the latest EMC and partner news releases, along with event photos, video and executive presentation slides available for download at: <http://www.emc.com/news/emcworld>

Spanning nearly one million square feet of exhibit and meeting space in Mandalay Bay's convention center in Las Vegas, Nevada, attendees will learn directly from EMC engineers, users and partners at more than 500 breakout sessions. Attendees can also explore the EMC World exhibit floor and Solutions Pavilion featuring more than 125 exhibitors and sponsors, representing a broad spectrum of the IT industry, including many of EMC's most strategic partners.

For the first time, EMC World will feature the EMC Innovation Showcase, providing a dedicated area for conference attendees to learn about EMC's innovation ecosystem and cutting-edge technologies under research and development in the company's worldwide offices. Technologies and processes will be showcased in an interactive fashion. Another first at EMC World 2008 is the EMC World Executive Forum that will bring together more than 200 executive-level attendees, providing them the opportunity to collaborate, discuss technology trends and strategy with EMC executives and innovation technologists.

EMC World 2008 kicks off on Sunday, May 18, with a welcome reception featuring a concert by platinum-selling, chart-topping recording artists The Goo Goo Dolls. The conference formally begins on Monday, May 19 with the opening of the EMC World exhibit floor and a keynote delivered by EMC Chairman, President and CEO Joe Tucci, who will address the impact that the ever-expanding digital universe will have on IT organizations of all sizes. He'll articulate how EMC's information infrastructure strategy is helping organizations and individuals intelligently and efficiently store, protect, and manage information so that it can be made accessible, searchable, shareable, and ultimately, actionable.

Additional executive keynotes will include Howard Elias, President, EMC Global Services & Resource Management Software Group who will discuss bringing automation to information infrastructure management; David Donatelli, President, EMC Storage Division who will focus on the latest innovations in storage; Mark Lewis, President, EMC Content Management and Archiving Division who

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will talk about helping customers navigate the complex content landscape to realize the full value of content management; Art Coviello, President, RSA, The Security Division of EMC will deliver a joint keynote with Brian Gallagher, Senior Vice President & General Manager, Symmetrix Product Group that will focus on trends in information security and the need to implement security holistically and linking it to information infrastructure.

On Wednesday, May 21, the topics will center on virtualization with a keynote by Dr. Stephen Herrod, Chief Technology Officer, VMware, focused on how virtualization can help overcome the challenges facing today's datacenters. The day will close with a customer appreciation event featuring acclaimed actor and comedian Billy Crystal.

In addition to the keynotes, educational sessions and exhibits, attendees can take advantage of the many opportunities for networking at EMC World including 44 "Birds of a Feather" sessions that offer users of EMC products and services a chance to share experiences, ask questions and learn from one another. The EMC Education Services group will be onsite to administer testing for EMC Proven Professional certifications.

More information on EMC World, including a full agenda and registration details are available at <http://www.emcworld2008.com>.

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Siemens PLM Software Announces Siemens PLM Connection Americas 2008

12 May 2008

Siemens PLM Software along with PLM World, Inc. announced Siemens PLM Connection Americas, an annual user and developer conference, will be held June 2 - 5, at the Gaylord Palms Resort and Convention Center in Orlando, Fla.

The annual user group conference, previously known as UGS Connection, is the longest running PLM industry conference, supporting one of the largest industry user communities. The conference targets users of NX™, Teamcenter®, Tecnomatix® and Solid Edge® software. More than 2,200 attendees are expected.

Jim Sistik, vice president, Information Technology, Visteon Corporation, a leading supplier of automotive components and integrated systems, will deliver a keynote address at the event. Sistik is responsible for IT strategy, daily IT operations and managing Visteon's alliance partnerships with IT service providers. Visteon has used Siemens PLM Software's technology as a core enabler of performance improvement. Siemens PLM Software was recently honored with a Visteon Important Partner Award for outstanding overall performance in the Non-Production category. ([see related release](#))

"Streamlining and connecting business processes through enterprise information systems is critical to compete in today's emerging markets," says Sistik. "Our company has effectively executed large-scale initiatives to standardize product development and operations practices globally. We have deployed a complete new suite of tools to drive efficiency and significantly reduce costs."

Main Conference

The conference continues to grow in technical content and attendance. The event will feature more than 600 educational sessions, including keynote presentations, technical sessions, product updates and hands-on-training. The majority of these sessions are best practices delivered by expert users.

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Presentations are organized in seven tracks to connect users with similar interests. These include:

- Velocity Connection: presentations cover the Velocity Series® portfolio, including Solid Edge.
- NX Connection: presentations cover digital product development.
- Teamcenter Connection: presentations cover digital lifecycle management.
- Tecnomatix Connection: presentations cover digital manufacturing.
- Management Connection: presentations focus on industry best practices.
- Simulation Connection: presentations cover digital lifecycle simulation.
- Developer Connection: presentations cover best practices for developers and partners who work with Siemens PLM Software technology.

“Siemens PLM Connection is a great event for our customers to share their knowledge and best practices,” said Dave Shook, senior vice president and managing director, Americas, Siemens PLM Software. “In addition to the rich technical content, customers can network with other industry leading companies that use our technology. This year we’ve also added a focused simulation track to address the increased industry focus on digital lifecycle simulation.”

Simulation Connection

A new Simulation track features more than 30 presentations on topics such as simulation process management, design analysis applications, advanced simulation through NX, Femap® and NX Nastran®, as well as test analysis integration. In addition, simulation keynote presentations include:

“Virtual Reality - it isn't real until you validate it” by Dr. Pete Avitabile, a professor at University of Massachusetts Lowell. Avitabile has more than 30 years of experience in design and analysis using FEM and experimental modal analysis techniques, with research focused on structural dynamics.

“Mechatronics for the 21st Century” by Dr. Razvan Panaitescu, who manages the Application Development and Mechatronic Support Department within Siemens Energy and Automation, Automation and Motion Division. Before joining Siemens he held professor tenures and research positions in Electric Drives and Control Engineering at various Universities in Romania, Norway and USA.

Developer Connection

The Developer Connection targets Siemens Solution Partners, end users and leading academic organizations that utilize Siemens PLM Software’s platform in their PLM efforts. Presentations include case studies as well as tips and techniques on integration, automation and implementation. Topics include: application programming interface, automation tools, interoperability and integration and service-oriented architecture (SOA).

For a more information, visit <http://www.siemens.com/plmconnection> or <http://www.plmworld.org>.

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Si2 to Host 4th Integrated Design Systems Workshop at DAC 2008

15 May 2008

The Silicon Integration Initiative (Si2) announced they will host the Integrated Design Systems

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Workshop at the Design Automation Conference (DAC) to be held at the Anaheim Convention Center in Anaheim, CA, from June 8-13, 2008. The “4th Integrated Design Systems Workshop - OpenAccess: A Platform for Continuous Evolution and Innovation” will be held on June 9, from 12PM – 4PM in Room 208A, and includes lunch.

As OpenAccess continues to deliver on the promise of interoperable EDA tools, its rich ecosystem is leading to exciting innovations that are changing the future of IC design systems. This workshop will explore some of these areas which are right now being developed by the OpenAccess community. Presentations and demonstrations will highlight these innovations and provide details on current functionality as well as planned progress. They include:

1. Electronic System Level (ESL) Extensions: Potential extensions to OpenAccess will allow ESL design systems to directly interface to OpenAccess-based physical analysis capabilities. These extensions will enable the mapping of system-level design representations on to their physical counterparts in OpenAccess to facilitate this analysis.

Speakers: John Darringer, IBM and Luca Carloni, Columbia University

2. OpenEngines: This proposed program would allow the interoperation of software engines and components that sit on top of the OpenAccess application programming interface (API) and information model. EDA vendors, academia, and end-user tool developers could write these engines without the need to build complete applications, and EDA users could integrate them into their OpenAccess-based design systems.

Speaker: Rob Mains, Sun Microsystems

3. Open Modeling Calculation Interface: The OpenAccess Coalition is working with the Open Modeling Coalition to develop a common interface to support consistent and accurate computation of library models for all EDA applications. This system provides direct access and bi-directional communication between OpenAccess applications and executable library models and parameters.

Speaker: Martin Foltin, Hewlett-Packard

4. Interoperable PCell Libraries (IPL): The IPL Initiative is creating and distributing an open-source IPL that resides in the OpenAccess database. For the first time in semiconductor industry history, IC designers will be able to operate on the same PCell libraries with tools from multiple vendors and any tools that they developed in-house.

Speakers: Ed Lechner, Synopsys and Ed Petrus, Ciranova

Other Si2-sponsored events at DAC include the Low-Power Workshop on June 8, from 4PM-7PM and the Si2 Member/Guest Meeting on June 9, from 6PM-8PM.

Links to more specific agendas and registration information can be found here:

<http://www.si2.org/?page=11>

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2008 European P2E Conference - Delivering on Strategies Call for Speakers

29 April 2008

Abstract Deadline: Monday, June 9, 2008

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Share your knowledge and best practices with your peers by speaking at the MESA 2008 European Plant-To-Enterprise Conference, November 3-4, 2008 at the Top Hotel, Prague, Czech Republic. This year's conference will focus on the theme, Delivering on Strategies, and showcase how manufacturers are enabling five key corporate initiatives:

- Lean Manufacturing
- Quality and Regulatory Compliance
- Product Lifecycle Management
- Real-Time Enterprise
- Asset Performance Management

Can you describe the relationship between these initiatives and the business processes they are designed to improve? Can you describe which production systems are key to their success? Can you identify the challenges that your project teams face on their journey, highlighting successes, failures and best practices?

The MESA community would like to learn from your experiences. Presentations should:

- Focus on how your production management/plant-wide IT systems support implementation of one or more of these five strategic initiatives. Subject matter may range from planning and implementation to challenges and results.
- Feature Manufacturer/Producer presenters or be a joint presentation between a Vendor & Manufacturer/Producer.

Additional Presentation Topics: Industry standards, solutions requirements development, justifying systems, technology selection, implementing solutions, metrics, and Service Oriented Architecture (SOA).

EMAIL YOUR ABSTRACT TO: euconference@mesa.org by **MONDAY, JUNE 9.**

Please include:

- Speaker's Name(s) - with company name, job title, email address, phone number
- Presentation Title
- 300 words or less description of proposed presentation theme and content

Questions?

Contact [MESA HQ](#) at +1(480) 893-6883 or via euconference@mesa.org.

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Financial News

Autodesk Reports First Quarter Fiscal 2009 Revenue of \$599 Million

15 May 2008

Autodesk, Inc. reported revenue of \$599 million for the first quarter of fiscal 2009, an increase of 18 percent over the first quarter of fiscal 2008. First quarter net income was \$95 million, or \$0.41 per

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diluted share, on a GAAP basis and \$117 million, or \$0.50 per diluted share, on a non-GAAP basis. Net income in the first quarter of the prior year was \$83 million, or \$0.34 per diluted share on a GAAP basis, and \$107 million, or \$0.44 per diluted share on a non-GAAP basis. A reconciliation between GAAP and non-GAAP results is provided at the end of this press release.

"Fiscal 2009 is off to a good start with our solid first quarter results," said Carl Bass, Autodesk president and CEO. "International markets, especially emerging economies, continue to underpin our overall revenue growth. We also continue to experience strong growth of our 3D products. Autodesk continues to drive innovative design technologies into a variety of industries - architecture, engineering, manufacturing, media and entertainment - and we will continue to work hard to shape the evolution of industry design trends such as Digital Prototyping and Building Information Modeling."

Operational Highlights

In addition to favorable currency exchange rates, Autodesk's performance in the first quarter of fiscal 2009 was driven by revenue from new seats, continued customer adoption of our 3D design solutions, and strong revenue growth in emerging economies.

Revenue from the emerging economies increased 41 percent over the first quarter of fiscal 2008 to \$101 million and represented 17 percent of total revenue.

The outstanding growth in emerging economies led to strong performance in our EMEA and Asia Pacific regions. EMEA revenue was \$259 million, an increase of 25 percent as reported over the first quarter of fiscal 2008, and 11 percent at constant currency. Revenue in Asia Pacific was \$149 million, an increase of 27 percent as reported year-over-year, and 18 percent at constant currency. Faced with continued economic headwinds, revenue in the Americas increased 4 percent over the first quarter of fiscal 2008 to \$191 million, as expected.

Combined revenue from the Company's model-based 3D products, Inventor, Revit, Civil 3D, NavisWorks, and Robobat, increased 37 percent over the first quarter of fiscal 2008 to \$146 million and comprised 24 percent of total revenue. Autodesk shipped approximately 35,000 commercial seats of its model-based 3D design products, including 11,500 commercial seats of Inventor and 24,000 seats of its Architecture, Engineering and Construction products - Revit, Civil 3D, and NavisWorks. In addition, revenue from 2D vertical products increased 16 percent compared to the first quarter of fiscal 2008.

Revenue from new seats increased by 23 percent compared to the first quarter of fiscal 2008.

Upgrade revenue and maintenance revenue combined increased 16 percent over the first quarter of fiscal 2008 to \$228 million. Maintenance revenue increased 33 percent compared to the first quarter of fiscal 2008 to \$167 million, or 28 percent of total revenue. Deferred maintenance revenue increased \$40 million sequentially and \$130 million compared to the first quarter of fiscal 2008. As expected, total upgrade revenue decreased 14 percent compared to the first quarter of fiscal 2008.

Business Outlook

The following statements are forward-looking statements which are based on current expectations and which involve risks and uncertainties some of which are set forth below. On May 1, 2008, Autodesk announced its intent to acquire Moldflow Corporation. Moldflow financials are not included in the following numbers.

Second Quarter Fiscal 2009

Net revenue for the second quarter of fiscal 2009 is expected to be in the range of \$600 million and \$610

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million. GAAP earnings per diluted share are now expected to be in the range of \$0.40 and \$0.42. This is slightly lower than our prior projection due to additional stock-based compensation expenses. Non-GAAP earnings per diluted share are expected to be in the range of \$0.52 and \$0.54 and exclude \$0.09 related to stock-based compensation expense and \$0.03 for the amortization of acquisition related intangibles.

Third Quarter Fiscal 2009

Net revenue for the third quarter of fiscal 2009 is expected to be in the range of \$605 million and \$620 million. GAAP earnings per diluted share are expected to be in the range of \$0.42 and \$0.45. Non-GAAP earnings per diluted share are expected to be in the range of \$0.53 and \$0.56 and exclude \$0.09 related to stock-based compensation expense and \$0.02 for the amortization of acquisition related intangibles.

Full Year Fiscal 2009

For fiscal year 2009, net revenue is expected to be in the range of \$2.45 billion and \$2.50 billion. Full year GAAP earnings per diluted share are now expected to be in the range of \$1.78 and \$1.88. This is slightly lower than our prior projection due to additional stock-based compensation expenses. Non-GAAP earnings per diluted share are still expected to be in the range of \$2.20 and \$2.30 and exclude \$0.32 related to stock-based compensation expense and \$0.10 for the amortization of acquisition related intangibles.

Earnings Conference Call and Webcast

Autodesk will host its first quarter conference call today at 5:00 p.m. EDT. The live announcement may be accessed at <http://www.autodesk.com/investors> or by dialing 800-561-2813 or 617-614-3529 (passcode: 38361016). An audio webcast or podcast of the call will be available at 7:00 pm EDT at <http://www.autodesk.com/investors>. This replay will be maintained on our website for at least twelve months. An audio replay will also be available for one month beginning at 7:00 pm EDT by dialing 888-286-8010 or 617-801-6888 (passcode: 41192095).

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Avatech Solutions Reports Third Consecutive Quarter of Profitability and Net Income of \$1.0 Million

15 May 2008

Avatech Solutions, Inc. announced financial results for its fiscal third quarter and nine months ended March 31, 2008.

For the third quarter of fiscal 2008, the Company reported revenues of \$12.8 million, compared to \$14.6 million in the prior-year quarter. Revenue included \$770,000 in commission from the Company's largest single software sale to date. Selling, general & administrative (SG&A) expenses were approximately \$4.7 million, or 37% of sales, compared to \$6.4 million, or 44% of sales, in the prior year quarter. As a percentage of sales, SG&A expense remained in line with the previous two quarters of fiscal 2008. Operating income was \$1.3 million, compared to a loss of \$111,000 for the prior year quarter. For the three months ended March 31, 2008, the Company reported net income of \$1.0 million, or \$0.05 per fully diluted share, compared to a net loss of \$200,000, or \$(0.02) per fully diluted share, in the same period in the prior year.

For the nine months ended March 31, 2008, the Company reported revenues of \$38.1 million, compared

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to \$39.0 million in the prior-year period. During the period, Avatech increased Service revenue by 11% to \$8.6 million as a result of the Company's focus on growing this important business group. SG&A expense was \$14.1 million, or 37% of sales, compared to \$17.0 million, or 44% of sales, in the prior year period. For the nine months ended March 31, 2008, operating income was \$3.1 million, compared to \$668,000 for the prior year period and net income for the period was \$2.3 million, or \$0.12 per fully diluted share, compared to \$0.3 million, or \$0.00 per fully diluted share, for the same period in the prior fiscal year.

George Davis, President and Chief Executive Officer of Avatech Solutions, said, "We are pleased with our net income and services revenue for the quarter and continue to concentrate on growing these areas. At the beginning of the year we stated that this would be a year of restructuring and focus, with an emphasis on profitability, and we are delivering to that end. Although we are disappointed with our top-line revenue results, and particularly our software product sales, we recognize that a combination of regional economic factors, workforce attrition and transition and vendor programs all contributed to the product sale shortfall. We have remained steadfast in containing expenses and improving margins, which are reflected in our performance during the quarter."

"For the year-to-date, we grew our Service revenue by 11% in 2008 over last year. This growth reflects our emphasis on improved utilization of our experienced engineers and their enhanced productivity. This is a core focus for growing our business, as it strengthens our relationships with customers by weaving our offerings deeper into their business and allows for greater interaction."

"Looking ahead, we anticipate continued profitability in the fourth quarter, and are focusing on returning to revenue growth, while delivering consistent net income in fiscal 2009. As of March 31, 2008, our balance sheet remains strong with \$4.1 million in cash, no long-term debt and an untapped credit facility of \$5 million. We believe this strategically positions us with the ability to complete accretive transactions that will strengthen our services businesses and enter new geographic markets. Currently, we are exploring potential targets that are profitable, possess total annual revenue between \$5 and \$15 million and have established capabilities," concluded Davis.

Conference Call Information

Avatech Solutions will hold a conference call to discuss its fiscal third quarter results at 11:00 a.m. ET on May 14, 2008. A replay of the call will also be available through May 21, 2008 and can be accessed by dialing (888) 286-8010 (Domestic) or (617) 801-6888 (International), and enter the passcode (50782613).

A live webcast of the call will be broadcast in the Investor Relations section of the Company's website, <http://www.avatech.com>. For those who cannot listen to the live broadcast, an audio replay of the call will also be available on the site for a limited time.

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Cimatron's Q1/2008 Results Release Scheduled for May 20, 2008

13 May 2008

Cimatron Limited announced that it will be releasing its Q1/2008 financial results on Tuesday, May 20th, 2008, before the US market opens.

Cimatron's management will host a conference call that same day, at 9:00 EST, 16:00 Israel time. On the call, management will review and discuss the results, and will also be available to answer questions by

investors.

To participate, please call one of the following teleconferencing numbers. Please begin placing your call at least 5 minutes before the conference call commences.

USA: +1-888-668-9141

Israel: 03-9180609

International: +972-3-9180609

For those unable to listen to the live call, a replay of the call will be available from the day after the call under the investor relations section of Cimatron's website, at: <http://www.cimatron.com/>

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Sopheon plc Interim Management Statement

15 May 2008

Sopheon plc issues its first interim management statement for the period since 1 January 2008 to the date of this announcement, in line with the requirements of the EU Transparency Directive.

As expected we had a productive first quarter this year, recording revenues 58% higher than in the first quarter of 2007, itself a relatively strong quarter by historic standards. Since the end of 2007 we have closed a total of 13 license orders and extensions, taking our total licensee base to 145. Our consultancy business continued to add new projects both in conjunction with new license orders, and through additional sales to existing customers. Our recurring revenue base has also continued to grow, amounting to over £2.8 million, up from £1.8 million in May last year. As in the past, our reported results in a particular period will be affected by the timing and size of individual sales; however this continues to be offset by increasing levels of repeat business from our growing client base. We are also encouraged that revenue visibility for the full year from contracted business and recurring revenue streams now stands at £5 million compared to full year revenues last year of £6.3 million; meanwhile we continue to work a full sales funnel with additional sales closures expected in the current quarter.

In March we launched the most significant new release of our Accolade software solution since it was introduced to the market more than six years ago. Many of the enhancements offered in this latest version of the software are based on our work with existing customers such as General Motors and Electrolux. These new capabilities position Accolade to move beyond the process manufacturing markets that we have historically targeted and into the large aerospace, defense and automobile sectors. The combination of Accolade and Vision Strategist, the product that came to us through the acquisition of Alignent Software, constitutes the first solution set in the industry to integrate strategic product planning and product development execution. Underlining this advance, AMR Research recently identified Sopheon as the most mature product portfolio management offering in the market today.

Our product advances have been matched by investment in new recruits that bring experience in the new markets we are pursuing. That said, we very much understand the global economic situation continues to remain uncertain, and we weigh each investment decision carefully. We are confident we are making the right choices, and remain positive about the outlook for the coming year.

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Valor Shows Significant Increase in Profitability and Another Quarter of Record Revenues in Q1/2008

12 May 2008

Valor Computerized Systems Ltd. announced its financial results for the period ending March 31, 2008.

Revenues in the first quarter of 2008 accumulated to \$10.7 Million, an increase of 3% as compared to \$10.3 Million in the first quarter of 2007.

The net profit increased by 91% as compared to the fourth quarter of 2007 – from \$0.8 Million to \$1.5 Million, and by 67% as compared \$0.9 Million in the first quarter of 2007.

EBITDA was \$1.7 Million in the first quarter of 2008 – an increase of 44% compared to \$1.2 Million in the previous quarter, and an increase of 16% as compared to \$1.4 Million in the parallel period of the previous year.

EBIT was \$1.1 Million in the first quarter of 2008 – nearly twice as in the previous quarter, and 23% more than in the first quarter of 2007.

Earning per Share (diluted) in the first quarter of 2008 was \$0.07, as compared to \$0.04 in the previous quarter and \$0.05 in the first quarter of 2007.

Some of the following statements are forward-looking in nature, and actual results may differ materially:

“Q1 was a good quarter for Valor, with results that were in par with our expectations,” said Ofer Shofman, Valor’s President and CEO. “We have been working to increase our profitability and are pleased to see that our efforts have been fruitful, showing a significant increase in both operational and bottom line profits, which nearly doubled as compared to the previous quarter. All this, despite Q1’s traditional reputation as being a weaker quarter, and in lieu of the US Dollar’s weakness against other currencies.”

“We continue to pursue our development and marketing plans, including establishment of OEM agreements with some of the world’s largest electronics assembly equipment vendors as means of expanding our distribution channels in a profitable manner. In addition, we continue to forge technological alliances with equipment vendors, which enable us to grow our customer base by expanding the scope of our solutions.”

“Overall, we are pleased with the quarterly results and continue to implement our growth strategies in all markets and regions.” Shofman concluded.

The complete financial report can be downloaded from the Investor Relations section on the Valor corporate website: <http://www.valor.com>

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Implementation Investments

American Icon Char-Broil Chooses Arena PLM to Help Introduce the Gas Grill All Over Again

14 May 2008

[Arena Solutions](#) announced that Char-Broil, the first name in gas grills, has chosen Arena PLM to help provide outdoor chefs with products that meet every cook’s style and budget. The company will rely

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upon Arena PLM to help manage bills of materials (BOMs), automate product change processes and collaborate with its facilities in Asia.

“Innovation, like the recent introduction of infrared grill technology at an affordable price, is a core value at Char-Broil,” said Thom Ward, director of marketing for Char-Broil. “Arena PLM’s simple to use software will help us create more inspired outdoor products that deliver superior taste, simplicity and efficiency.”

Char-Broil considered several vendors to find the PLM software that best met its requirements. The company selected Arena PLM after participating in Arena’s “try and buy” program that enables the company to try the software with its own data before buying it. Arena Solutions is unique in allowing organizations like Char-Broil to validate Arena PLM against specific company requirements before making any investment, thus lowering companies’ risk to their business. Char-Broil quickly realized Arena PLM is faster, easier and less expensive to deploy than traditional client/server software. Delivered on a world-class, on-demand architecture, Arena PLM lets Char-Broil focus on developing world-class gas grills rather than buying, managing and maintaining expensive IT hardware.

“The entire Arena team is excited to work with such a well-known and successful company as Char-Broil. We are huge fans of its products, and appreciate Char-Broil’s drive for innovation and desire to perfect the grilling experience,” said Craig Livingston, chief executive officer at Arena Solutions. “By using award-winning Arena PLM to manage BOMs and automate change processes, Char-Broil will continue to improve product quality, minimize errors and increase the pace of innovation.”

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Burt Hill Receives Revit BIM Experience Award for Sustainable Design of Major Education, Healthcare and Commercial Projects

14 May 2008

[Autodesk, Inc.](#) announced that Burt Hill, an architecture, engineering and design firm, has been selected to receive a Revit BIM Experience Award. At an Autodesk customer appreciation event to be held this evening, the firm will be honored for its successful use of the Revit platform for building information modeling (BIM) to design buildings that have earned Leadership in Energy and Environmental Design (LEED) ratings from the U.S. Green Building Council (USGBC). The Revit BIM Experience Award is presented to commercial firms, educational institutions and individuals for innovation and excellence in implementing the Autodesk Revit platform (which includes Revit Architecture, Revit Structure and Revit MEP software applications) on one or more projects.

"The Revit platform for BIM has made it possible for us to achieve complete design integration and model-based analysis, both of which are crucial requirements for performance-based design," said Mark Dietrick, director of research for Burt Hill. "We are using the information-rich digital model created with Revit Architecture in combination with sustainability analysis tools very early in the schematic design phase to evaluate specific aspects of a green design. This allows us to balance requirements for building energy performance against cost, schedule, and experiential aspects of the design."

Burt Hill's services include architecture, engineering and master planning.

With more than 1,000 professionals operating from 10 locations in the US and offices in Abu Dhabi, Dubai and India, Burt Hill offers clients expertise in sustainable design, energy management and technology integration. The firm has a longstanding history of commitment to sustainable design and

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was the first architecture/engineering firm to join the USGBC. Some of the firm's notable projects include the 26-acre Canal Point Master Plan, Dubai, UAE; the Biomedical Science Tower, Pittsburgh, PA; and the Advanced Technology and Learning Center for the Cincinnati State Technical and Community College.

Autodesk BIM solutions used by the firm include Revit Architecture, Revit Structure, Revit MEP, Autodesk NavisWorks and AutoCAD Civil 3D.

BIM is an integrated workflow built on coordinated, reliable information about a project from design through construction and into operations. By adopting BIM, architects, engineers, contractors and owners can easily create coordinated, digital design information and documentation; use that information to more accurately visualize, simulate, and analyze performance, appearance and cost; and reliably deliver the project faster, more economically and with reduced environmental impact. Case Technologies provided training services to help Burt Hill with its transition to BIM.

BIM Used for LEED Certified School District Project

Burt Hill is currently designing a new Literacy Center in Springfield, Penn.

Located on a wooded hillside, the 50,000 square-foot facility is scheduled to open April 2010 and includes two wings designed to wrap around a mature grove of oak trees. A single-story wing will house classrooms and an art center, and a three-story wing will include further classrooms, a library, offices, and spaces for special education and multipurpose activities.

In addition to the demanding budget and schedule constraints that typify school building projects, the plan for the Literacy Center required that it achieve a LEED certification. The Burt Hill team leveraged Revit Architecture and Integrated Environmental Solutions (IES) Virtual Environment tools to analyze the project model. The results were used to determine the optimal size, orientation, location, and glazing of the windows to provide effective daylight levels, reduce glare and maintain comfortable temperatures with as much energy efficiency as possible.

"Burt Hill is one of the earliest adopters of BIM and Revit Architecture, and we're particularly pleased to present them with this award," said Jay Bhatt, senior vice president, Autodesk AEC Solutions. "Burt Hill's use of the Revit platform to create green building projects means that they can analyze and optimize building performance early in the design phase, which underscores the value of BIM for sustainable design."

The Revit BIM Experience Award celebrates building industry professionals and educators around the world who are helping to drive transformation of the building industry through building information modeling. Autodesk honors firms with this award for innovation and excellence in implementing the Autodesk Revit platform (including Revit Architecture, Revit Structure and Revit MEP software applications) for building information modeling on one or more projects.

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Delcam Software Helps Crosby Composites Produce High-Accuracy Parts

16 May 2008

Switching to Delcam's CAD/CAM software has helped Crosby Composites to produce composite components to levels of accuracy rarely seen in the industry. Owner Paul Crosby now uses this ability to finish machine every part to tolerances between 0.1 and 0.25mm as the key differentiator for his

business.

Mr. Crosby introduced 3D modelling and machining around eight years ago. Before then, he had thought the systems were too expensive but CAD/CAM quickly became the normal way to do things. "I started with PowerSHAPE," he recalled. "The user-friendly interface was what sold it to me. I could use it immediately for basic tasks and found it very easy to learn how to do more complex modelling operations. I then took PowerMILL on a thirty-day trial. At the end of that time, I didn't need to think twice about adding it."

"Since we swapped over to Delcam software, we have gone from strength to strength," claimed Mr. Crosby. "The software is so powerful and so easy to use that it is difficult to criticise it."

"PowerMILL is the only practical way to machine repeatably to the level of accuracy we need," he added. "The F1 market generally requires a maximum run of sixteen parts. Unless you can be very efficient, it is difficult to justify the cost of machining everything."

The latest addition to the range of Delcam software at Crosby has been the PowerINSPECT On-Machine Verification software. "I saw a demonstration and immediately decided we needed it," said Mr. Crosby. "The software has been a great investment."

With composites, machined holes and pockets tend to be undersize because the material relaxes when it is cut. This effect is difficult to predict because it is impossible to cut all the fibres in the same orientation. To overcome this problem at Crosby, the initial machining operation is followed by an inspection on the machine tool with PowerINSPECT. This shows how much more material needs to be removed and enables the required extra toolpaths to be generated in PowerMILL.

For a typical component, with between 20 and 30 holes, a further cycle of inspection and machining may be needed to produce all the dimensions to the required tolerance. However, for subsequent parts, the complete machining sequence can be repeated and the results checked with a final inspection.

Apart from the increase in accuracy possible with this approach, another big benefit is that all the machining and inspection can be completed on the machine tool on a single fixture. According to Mr. Crosby, it is impossible to maintain the necessary tolerances when moving between a series of fixtures, while using multiple set-ups on different fixtures would also take much longer.

The first set of seventeen components produced with this method was supplied to one of the F1 teams and fitted onto the car with no clashes or re-work. It was the first time in the team's history that this had happened with any set of composite parts from any supplier.

"Since then we have used On-Machine Verification as much as we possibly can," said Mr. Crosby. "It ensures that we can catch any mistakes before they reach our customers. In the six months since we started with this approach, we have only had one part rejected and that was because of just one undersize hole."

Crosby has recently added its sixth CNC machine, a five-axis CMS router, and is already looking into expanding further. "We will continue to use technology to do things better and more accurately," concluded Mr. Crosby. "Once the teams realise the level of accuracy that we can provide, they will soon switch from other suppliers that regularly send boxes of bits that don't fit together."

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DiaSorin Seeks Unified Risk Assessment Using Dyadem Software

12 May 2008

DiaSorin, a global provider of clinical in-vitro diagnostic medical devices, has turned to [Dyadem](#) to improve its risk assessment and ensure the quality of its medical devices. Dyadem is assisting DiaSorin through the use of its FMEA-Med software to improve its risk assessment processes and ensure regulatory compliance.

FMEA-Med is a software solution that delivers Failure Mode and Effects Analysis (FMEA) for medical devices and pharmaceutical manufacturers. Dyadem solutions improve quality and prevent potential flaws in hardware design, manufacturing and processes in a variety of industries, including aerospace, chemical and automotive. DiaSorin selected FMEA-Med to improve product designs analysis for defects, and to optimize manufacturing processes by creating consistent quality standard templates that are used throughout the company's headquarters in Italy and facilities in Germany and the United States. These templates bring a unified methodology to DiaSorin's worldwide processes and standardize risk management.

The global scale of DiaSorin's operations require the company to comply with a host of domestic and international quality regulations, including the IVD Directive, CE Marking, ISO 14971 and various Food and Drug Administration requirements in the United States. These regulations require documentation of risk assessment procedures and monitor the quality of incoming medical devices. For example, the FDA requires the inspection of foreign medical supply facilities before their products are sold in the United States.

DiaSorin's facilities operate independently from each other, but needed a common way to assess risk and unify compliance. Individual teams are able to improve their efficiency through the use of standard Dyadem templates used across the organization. Previously, DiaSorin was using standard spreadsheet programs that allowed few customizations for medical device manufacturers. Now, DiaSorin is able to transfer knowledge and processes across facilities, allowing for easy adjustments to changes in production locations. The result is a unified approach to quality.

When evaluating potential solutions, DiaSorin used Dyadem Web demonstrations to view FMEA-Med's capabilities. DiaSorin is now working with Dyadem experts on-site to deploy the software, create process templates and train staff.

"Last year alone, the U.S. FDA issued 20 recalls of medical devices - an alarming increase compared with five years ago. DiaSorin is leading its industry in setting high standards for quality and ensuring consumer safety," said Kevin North, president and CEO of Dyadem. "With the world's top ten medical device manufacturers on our client list, Dyadem understands the unique needs of medical device companies and the scrutiny they are under. We are working closely with our customers to ensure that medical device quality is not an afterthought. "

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HiSilicon Selects Synopsys as IP Vendor Of Choice for SoC Designs

13 May 2008

Synopsys, Inc. announced that HiSilicon Technologies, an IC design company for communication networks and digital media, has chosen Synopsys' [DesignWare® IP](#) as the de-facto standard for HiSilicon's system-on-chip (SoC) designs. The multi-year agreement gives HiSilicon access to

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Synopsys' broad portfolio of DesignWare IP such as PCI Express, USB and DDR protocols, which enable HiSilicon to reduce risk and speed time-to-market for their communication infrastructure and consumer electronics designs.

"After evaluating several competitive offerings, we selected Synopsys because of its established leadership in delivering high-quality IP, which has been silicon-proven in a wide range of high-performance SoC designs," said Teresa He, senior vice-president at HiSilicon Technologies. "Combined with Synopsys' breadth of complete solution offerings and excellent technical support, this made Synopsys' DesignWare IP an obvious choice for us."

"As the leading provider in connectivity IP, we continue to provide customers such as HiSilicon with comprehensive, high quality solutions that reduce design risk and enable them to develop complex chips on schedule," said Joachim Kunkel, vice president and general manager of the Solutions Group at Synopsys. "We appreciate HiSilicon's trust in Synopsys and welcome the opportunity to help them ramp their SoC designs to volume production faster."

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Mentor Graphics Announces 20th Annual PCB Technology Leadership Awards Program Winners

14 May 2008

Continuing in its tradition of promoting and recognizing printed circuit board (PCB) design excellence, Mentor Graphics Corporation announced winners of its 20th annual PCB Technology Leadership Awards (<http://mentor.com/go/tla>) ceremony during the PCB Design Conference East in Tinley Park, IL. Started in 1988, this program is the longest running competition of its kind in the electronic design automation (EDA) industry. It recognizes engineers and computer aided design (CAD) designers who use innovative methods and design tools to address today's complex PCB systems design challenges and produce industry-leading products.

"Mentor Graphics' PCB Technology Leadership Awards provides the opportunity to showcase the industry's most innovative and talented designers worldwide," said Henry Potts, vice president and general manager, systems design division, Mentor Graphics. "The high volume of design entries truly reflects the dramatic increase in design complexity and functionality seen in today's electronic products. This design diversity and complexity further validates the need for the continued innovation of design automation technologies and processes. It is very rewarding to see our tools helping to develop and deliver the next generation of electronics products."

Industry experts judged entries from 20 countries in six categories representing a wide variety of industries. New this year is the recognition of "Runners-up," since there were so many competitive entries that were mere points from the winning submissions. The PCB industry expert judges included Happy Holden, senior technology specialist of Mentor Graphics; Gary Ferrari, technical support director, FTG Circuits; Pete Waddell, vice president of UP Media, publisher of Printed Circuit Designs & Fabrication Magazine; and Rick Hartley, senior principal engineer, avionics division of L-3 Communications.

2008 Technology Leadership Award Winners

Category: Best Overall Design

Company Name: Alcatel Lucent (France) using Expedition® Enterprise

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Design Team: Laurent Moquet, Jean-Claude Simon

Category: Consumer Electronics & Handhelds

Company Name: Philips Consumer Lifestyle (Belgium) using Board Station®, XtremePCB™

Design Team: Pascal Pardo, Goedgebeur Emmanuel, De Pauw Bertrand, De Keyzer Randal, Vanderghote Jean-Christophe, Parmentier Jurgen

Runner Up: Matsushita Electric Industrial Co., Ltd. (Japan) using Expedition Enterprise

Category: Industrial Control, Instrumentation, Security & Medical

Company Name: GE Fanuc Intelligent Platforms (USA) using Expedition Enterprise, XtremePCB

Design Team: Jack Henslee, Fred Girgenti, Owen Wells Runner Up: CiBOARD Electronic GmbH (Germany) using Expedition Enterprise, HyperLynx®

Category: Military & Aerospace

Company Name: DRS Technologies (Canada) using Expedition Enterprise, HyperLynx

Design Team: Robert Turzo, Andre Demers Runner Up: L-3 Communications (USA) using Expedition Enterprise, HyperLynx

Category: PC Computers and Peripherals

Company Name: ACCM Computing (Egypt) using Expedition Enterprise

Designer: Ahlmed Essam

Runner Up: Xerox Corporation (USA) using Expedition Enterprise

Category: Telecommunication Switches, Network Servers, Base Stations and Computer Mainframes

Company Name: Broadcom Corporation (USA) using Expedition Enterprise

Design Team: John Mehlmauer, Michael Hurt

Runner Up: RAD Data Communications Ltd. (Israel) using Expedition Enterprise

Category: Transportation and Automotive

Company Name: AVL List GmbH (Austria) using Board Station, I/O Designer™

Design Team: Wolfgang Rinner, Gernot Fernitz, Ewald Schenkirsch

Runner Up: Johnson Controls (USA) using Expedition Enterprise, Quiet™ Expert

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Moriroku Streamlines Design Process and Increases Productivity with Dassault Systèmes' CATIA PLM Express

13 May 2008

Dassault Systèmes (DS) announced that Moriroku Company, Ltd. ([Moriroku](#)), a leading manufacturer of industrial chemicals and plastics, supplier of automotive parts based in Japan, has streamlined its design process and dramatically increased productivity with Dassault Systèmes' CATIA PLM Express.

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A manufacturer of plastic interior and exterior auto parts, Moriroku faced continuous time-to-market reduction pressure in the increasingly global automotive supply chain. To further boost its competitive edge, Moriroku selected the Automotive Supplier Offer based on CATIA PLM Express, looking to standardize its design process, shorten design time, and improve product development cycle. Using CATIA Functional Molded Part - included in Auto Supplier Offer - history-free construction and features with discipline oriented behaviour enabled concurrent design between its styling and mechanical designers. Their ability to share accurate design concept and intention throughout the design process resulted in high productivity gains at design creation, true parallel work for the design team, and a 30 percent design time reduction. Also, with 2D Layout for 3D Design, 2D design is seamlessly reflected in 3D, which helped to standardize the design process.

“The Automotive Supplier Offer was the best choice for us, because it provides all the functions we need at a reasonable price,” says Tetsuo Toda, Executive Officer, Deputy General Manager of Production Headquarters and General Manager of Technical Research Center, Moriroku Company, Ltd. “Deploying it enabled us to accelerate our product development process standardization.”

“We are pleased that Moriroku chose Automotive Supplier Offer to improve its development process,” says Nikos Calfacacos, general manager, Dassault Systèmes Japan. “In the competitive auto industry, both high quality products and shortened time to market are indispensable. We are committed to providing the value of PLM to small and mid-sized companies as well as to helping them increase their competitiveness. DS Solutions were implemented through a collaborative effort from DS and Argographics, a DS Value Added Reseller in Japan.”

Automotive Supplier Offer based on CATIA PLM Express is the ideal solution for companies the size of Moriroku, who are turning to PLM for a simple way to bring high quality innovative products to market faster than ever while reducing costs. In addition to CATIA Functional Molded Part, Automotive Supplier Offer includes CATIA 2D Layout for 3D Design with which the same data can be used throughout end-to-end processes from upstream initial layout to downstream detailed design thanks to the link between 2D and 3D, bringing transformation to the design process. This supports 2D users in moving to 3D easily. Automotive Supplier Offer also includes data management functions that enable customers to capitalize its intellectual properties and reuse it effectively.

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PTC Signs Memorandum of Understanding on Education Cooperation with Chinese Ministry of Education

12 May 2008

[PTC](#) announced that it has signed a Memorandum of Understanding (MOU) on education cooperation with China’s Ministry of Education (MOE). As part of the memorandum, PTC’s software technologies will be incorporated in many education and research programs within China’s leading universities, as well as its primary, middle schools, high schools and vocational schools. PTC is committed to furthering its support of engineering education in China by helping Chinese students of all ages increase their technological literacy, mastering technological skills to become qualified, talented engineers.

In a meeting to discuss the partnership of PTC with MOE, Wu Qidi, vice minister of the Education Ministry and John Stuart, PTC senior vice president of global partners and education, analyzed how to cultivate engineering talents across all education levels in China. During the meeting, they assessed how

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to improve engineering education and design skills for college students soon to enter the workforce as well as how to encourage science education in younger students. Also in attendance from MOE were Mr. Cao Guoxing, director-general, Department of International Cooperation and Exchange; Ms. Liu Ju, deputy director-general, Department of Higher Education; Mr. Wang Jiping, deputy director-general, Department of Vocational & Adult Education; and Mr. Li Tianshun, deputy director-general, Department of Basic Education.

According to the MOU, PTC will provide Pro/ENGINEER®, Windchill®, Arbortext® and Mathcad® software and related training to numerous Chinese universities and colleges. PTC will further strengthen its partnership with several higher education institutes and establish PTC Academies, whose focus will be on design skill training. Additionally, PTC will continue to focus on early technology education, providing free Pro/ENGINEER design software and training to primary, middle schools and high schools throughout China.

“As China’s global economy continues to grow, the country’s manufacturing industry has also shown unprecedented development towards a transition from 'Made in China' to 'Innovated in China.' In order to support this growth, engineers with advanced design skills are needed,” said John Stuart, senior vice president, global partners and education, PTC. “We are very pleased to partner with China’s Ministry of Education, to share PTC’s product development software and teaching programs and help students – whether at the college, vocational school or secondary school level – receive the best product development education and practical design skills. In turn, we’re nurturing more innovative talent for the entire industry, worldwide.”

Mr. Stuart also thanked MOE for awarding PTC the Certificate of Honor for PTC’s contribution to the betterment of education in China.

As part of the MOU between PTC and MOE, PTC and Tsinghua University held a ceremony to commemorate the establishment of the PTC Academy at Tsinghua University, which extended their long-term partnership for years to come. PTC announced that it will donate Pro/ENGINEER to Tsinghua University and its CAD Teaching Centre to facilitate advanced design research and training in engineering education. The University will incorporate the advanced design concepts and methods of PTC software into its courses and use Pro/ENGINEER as its main software in its engineering education program.

“Tsinghua University and PTC have worked together for more than ten years helping to prepare future generations of talented engineers in China,” said Yuan Si, vice president of Tsinghua University. “We hope to continue our strong collaboration by offering our students more advanced manufacturing design skills, enabling them to become talented, world-class engineers.”

Since 1995, PTC has supported more than 150 Chinese universities and vocational schools. Universities such as Tsinghua University, Beijing Institute of Technology, Nanjing University of Science & Technology, Harbin Engineering University, Huazhong University of Science & Technology, Shanghai Jiaotong University and South China University of Technology all utilize PTC software for teaching and research activities. Since signing the MOU with MOE, PTC has already donated Pro/ENGINEER to more than 100 schools in Beijing, Tianjing, Hebei, Shandong province and Hong Kong. All of these efforts have contributed to the development of Chinese students’ technological literacy and design skills, and the growth of industry talents in China.

About The Ministry of Education of the People’s Republic of China

The Ministry of Education of the People’s Republic of China is a central government agency under the

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State Council, responsible for China's educational undertakings and language work.

About Tsinghua University

Tsinghua University was established in 1911 originally as "Tsinghua Xuetang." Currently, the university consists of 44 departments with 61 majors distributed in 13 schools, including the schools of sciences, architecture, civil engineering, mechanical engineering, information science and technology, humanities and social sciences, economics and management, law, arts and design, public policy and management, and applied technology.

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Renesas Adopts Cadence SOC Encounter for Large Scale Complex Chips and Flip-Chip Design

12 May 2008

[Cadence Design Systems, Inc.](#) announced that Renesas Technology Corp. has successfully taped out its most advanced and large-scale system-on-chip (SoC) design to date using the Cadence SoC Encounter™ system. Encounter's complete end to end digital implementation and analysis solution, including innovative design planning, hierarchical modeling, and flip-chip technologies, dramatically reduced design cycle time and silicon costs while accelerating overall timing closure and time to market.

"With SoC Encounter's exceptional memory capacity and fast turnaround time, we were able to tape out our most significant and complex hierarchical design," said Hisaharu Miwa, general manager, Design Technology Division LSI Product Technology Unit at Renesas. "Given the complexity of this design and our aggressive schedule constraints, using a traditional ILM approach to hierarchical design was infeasible, and a new approach was required. SoC Encounter's innovative hierarchical layout handling and 'dynamic' timing modeling technology coupled with its unique automatic floorplan synthesis, and integrated flip-chip features gave us a way to meet our performance and schedule goals while reducing our die-size and manufacturing costs."

"SoC Encounter continues to extend its current lead in providing advanced features and automation to address the needs of very large scale, high-performance, and complex chip design," said David Desharnais, group director of IC Digital product marketing at Cadence. "Renesas' experience and results with SoC Encounter, demonstrates their confidence in its ability to meet and exceed their requirements for advanced designs."

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Shanghai Dianji University Receives In-Kind Software Grant with a Commercial Value of US\$46 Million From Siemens PLM Software

14 May 2008

[Siemens PLM Software](#) announced an in-kind software grant with a commercial value of US\$46 million to Shanghai Dianji University (SDJU) to enrich their engineering curriculum and open a new Training Center for China and beyond. The in-kind investment was made through the company's GO PLMTM Program and includes engineering software, student/instructor training and an NXTM Certification Program.

Siemens PLM Software's NX digital product development software supports product design, through engineering and ultimately manufacturing. NX helps customers cut costs, while improving product

quality and profitability.

“SDJU is tremendously thankful for this overwhelming in-kind grant and to open the SDJU/Siemens PLM Software NX Training Center,” said Dr. Jian Guo Xia, president of SDJU. “On behalf of SDJU, I want to express sincere appreciation to Siemens PLM Software for providing this industry leading software for our academic institution. Innovative development combined with extensive industry experience incorporated over several decades has made NX a comprehensive product development tool. It is not only strong in advanced design capabilities, but also provides students with experience in the latest manufacturing technology and theory.

“Our teaching and scientific research work will benefit significantly from using Siemens PLM Software in our courses, where students and researchers will be able to develop real-world products and gain the latest knowledge of PLM processes. We expect graduating students who pass the NX Certification Examination will have numerous job opportunities in the rapid growing Chinese Manufacturing Industries.”

“Today’s leading manufacturing and technology companies compete on the basis of time to market, product cost, quality and innovation,” said Chuck Yuan, senior vice president and general manager, Greater China, Siemens PLM Software. “It’s quite clear that today’s best students in top programs, like the program at SDJU, must have the opportunity to gain experience with technology that supports these objectives.”

GO PLM Program

GO PLM provides PLM technology to more than 950,000 students yearly at nearly 9,300 global institutions, where it is used at every academic level – from middle schools to graduate engineering research programs. For more information on GO PLM and the partners and programs it supports visit http://www.plm.automation.siemens.com/en_us/about_us/goplms/index.shtml

About Shanghai DianJi University

Shanghai DianJi University was founded in 1953. The creation of “Cai Detai Teaching Method”, which was popular all over China, helped the school gain precious educational experiences. Liu Shaoqi, former leader of PRC, inspected the school in 1958 and commended its achievement. He confirmed the school’s educational mode and summarized it as “integrating school with factory and focusing on both teaching and production” The school was one of the first three schools nationwide with the privilege to start experimenting 5-year higher vocation education approved by the former National Education Committee. “With approval of the municipal government of Shanghai, the school was upgraded in September of 2004 to a university with full undergraduate programs.

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‘Snakehead’ Camera System, Designed in SolidWorks, Soars in New Bond Film

12 May 2008

A breakthrough movie camera system called the Snakehead, designed entirely in SolidWorks® 3D CAD software, is resetting the boundaries of cinematography, immersing viewers more deeply than ever in hair-raising aerial action.

With the Snakehead, pilots for the first time can fly as aggressively as they dare without sacrificing the drama of the shot. SpaceCam Systems, Inc. of Los Angeles debuted the Snakehead last month in the

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canyons of Baja, Mexico, for the upcoming James Bond film “Quantum of Solace.” The month-long shoot was “wildly successful,” according to veteran aerial cinematographer Dwayne McClintock, also a mechanical engineer who co-designed the system. “We shot some astonishing footage, like nothing you’ve seen before,” he said. The Snakehead also worked “flawlessly” on a TV commercial in which a Jeep rolled out the door of a cargo plane 10,000 feet above the desert sand.

With a 360-degree remotely controlled spherical range of view, the patented Snakehead is the first plane-mounted gyroscopically stabilized periscope, compatible with various movie and HD cameras and providing super high quality resolution. The lens system maintains a level horizon, solidifying a frame of reference to keep viewers in the story. Traditional aerial cinematography approaches – for example, a fixed periscope on a Lear jet – distract and sometimes sicken viewers by depicting a seemingly lurching horizon. If the filming plane needs to adopt the point of view of a chasing aircraft, however, Snakehead operators can turn off the stabilization to convey its maneuvers.

“As they will see in the Bond film, the Snakehead puts moviegoers in the middle of the action instead of just observing, or worse, being virtually tossed around in the theater,” said McClintock. “The Snakehead is by far the most challenging design I’ve ever attempted. SolidWorks software’s efficiency made the work so much easier than it could have been. SolidWorks let us design a better product by cycling through dozens of iterations and working with flexible subassemblies. We had many original crazy and weird-looking parts that, thanks in large part to SolidWorks, went together seamlessly the first time. The Snakehead exceeded our expectations.”

In the Bond filming, a Piper Aerostar 700 with Snakeheads on the nose and tail filmed two planes in a aerial chase sequence and dogfight.

[SpaceCam](#) collaborated on the design with engineers at Ballista Inc. of Westlake Village, Calif., which engineered the optics, also using SolidWorks software. The Snakehead posed several significant design challenges for the combined team, including battering from weather and debris, mechanical rotation, and image inversion (Ballista used SolidWorks to create a fourth, “derotation” prism to keep the filmed image upright in the periscope).

“What I like most about SolidWorks is the flexibility,” said Walt Caldwell, vice president of production and operations for Ballista. “Whenever you start a project with nothing but an idea you wind up in a different place than you thought you would, constantly making multiple iterations with major changes. SolidWorks lets us quickly change a component and replace it with a new one, and all the mates and parent/child relationships are intact. SolidWorks makes major changes easy, without having to start the model all over again.”

“The Snakehead is a revolutionary product,” said Rainer Gawlick, vice president of worldwide marketing for SolidWorks Corporation. “It’s inspiring to see our software help launch an innovation that will have a resounding impact on cinematography and entertainment.”

Ballista and SpaceCam rely on authorized SolidWorks reseller GoEngineer for ongoing software training, implementation, and support.

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Socle Technology, Inc. Adopts Cadence Low-Power Solution to Address 65NM Power Efficiency Challenges

12 May 2008

Cadence Design Systems, Inc. announced that Socle Technology, a leading system-on-chip design service and solution provider in Taiwan, has adopted the Cadence Low-Power Solution for the Socle SoC-ImP® solution, an ultra-deep submicron implementation platform for SoC design. The Cadence Low-Power Solution enables Socle to leverage innovative low-power techniques to solve power challenges at 65 nanometers and below.

The Cadence Low Power Solution, which is based on the Si2-standard Common Power Format (CPF), has already been used by Socle to tape out an advanced 65-nanometer design with low-power techniques, including multiple power domains, multi-voltage, multi-Vt, power shut-off and retention, resulting in higher productivity while significantly reducing power. The tapeout involved a 65-nanometer ARM926EJ-S®-based media application processor on a Chartered Semiconductor Manufacturing Ltd. process.

"This important tapeout required a comprehensive low-power solution to analyze and manage power throughout the flow, while accelerating the design cycle," said Chou-Te Kang, vice president of R&D of Socle. "The Cadence Low-Power Solution helped our design teams predict and correct problems early in the design process and achieve faster time to market. This successful design experience has led us to join the Power Forward Initiative (PFI), which allows us to work closely together with other industry leaders in delivering high-quality, low-power solutions to our customers."

Socle used the complete Cadence Low-Power Solution, including Incisive® Enterprise Simulator, Incisive Enterprise Manager, Universal Verification Components (UVC), Incisive Plan-to-Closure Methodology (IPCM), Encounter® Conformal Low Power, and SoC Encounter GXL. The integrated, front-to-back low-power verification helped Socle reduce risk and improve design cycle time.

The IPCM, which incorporates the Open Verification Methodology (OVM), helped to more accurately predict the development effort with an automated plan- and metric-driven approach to system-level verification closure. SOC Encounter GXL extended that advantage into physical implementation by providing an integral platform to implement low-power intent while concurrently addressing variation issues at 65 nanometers. Describing designers' power intent with the industry-standard CPF helps eliminate manual effort and the potential for human error in each step of the flow. As a result, Socle was able to harness the efficient and integrated value in the full Cadence Low-Power Solution.

"We are pleased that Socle has adopted the CPF-enabled Cadence Low-Power Solution into their design flow and joined PFI," said Willis Chang, country manager of Cadence Taiwan. "We look forward to working with Socle on additional advanced projects and helping them to realize their aggressive project goals through better schedule predictability and improved team productivity."

About Power Forward Initiative

"The Power Forward Initiative, which has more than 25 member companies, is an industry initiative sponsored by Cadence and has the goal of enabling the design and production of more power-efficient electronic devices. The initiative includes companies representing a broad cross section of the design chain including system, semiconductor, foundry, IP, EDA, ASIC and design services companies. CPF was contributed by Cadence to the Si2 Low-Power Coalition in December 2006 and CPF 1.0 is now available as an Si2 standard to the industry at large. The Initiative has also published A Practical Guide

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to Low-Power Design — User experience with CPF which is aimed at educating the broad design marketplace in utilizing advanced low-power design techniques. The Guide is available free of charge at <http://www.powerforward.org>.

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Spiegel Brands Goes Deep in the Supply Chain with Yunique PLM

13 May 2008

[Yunique Solutions Inc.](#) reports that Spiegel Brands Inc., the leading U.S. direct marketer of women's apparel, is extending the use of its software solutions in support of a major corporate initiative aimed at speeding new products to market and enhancing its ability to meet fast-changing consumer demand. Specifically, the apparel, footwear, accessories, and home products retailer is leveraging the collaboration and process management aspects of the Yunique software to tightly integrate independent vendors into new regional product teams that will perform all design-through-development processes in close proximity to Asian production facilities. By creating deeper, real-time relationships with its suppliers, Spiegel Brands expects to tap into greater product innovation, create operational transparency, and gain a more efficient and proactive supply chain.

Spiegel Brands implemented Yunique's web-based plmOn™ software in early 2006 to manage the merchandising, design, technical design, product development and sourcing functions in its Manhattan headquarters. This initiative was followed with the deployment of srmOn™, the online collaboration component of the integrated system used to electronically integrate buying offices and trading partners in Hong Kong, Northern and Southern China, and India into the product lifecycle process.

“We needed a system built on a modern, open platform that provided for global collaboration”, noted Jose Sanz, director of technical design systems, processes, & calendars at Spiegel Brands. “Our old home-grown system would not allow us to connect outside of our headquarters. In Yunique, we found a great fit that allowed us to integrate our Mac-based designers as well as our entire universe of buying offices and trading partners. We can manage our apparel, footwear, home and accessories lines with this single solution. Not only can we create tech packs at triple the rate of before with the same number of people, we can now share them instantaneously online with our global teams.”

“We believe that the Yunique technology can help us develop our supply chain into a powerful competitive edge,” added Sanz. “The plmOn and srmOn systems help us to quickly calibrate the new regional teams with the information and processes they need to serve as ‘real’ business partners. Instead of relying on faxes and emails to communicate, our partners now work directly with us in a shared system with one definitive source of product information.”

“We are pleased to provide a platform for business process innovation at Spiegel Brands”, said Darioush Nikpour, vice president of business development for Yunique Solutions. “We pioneered supplier relationship management capabilities in our system years ago in anticipation of what we saw as a significant opportunity for fashion companies to move beyond simple buyer-seller relationships to value-added partnerships. We are proud to have our technology serve as an enabler to industry leaders such as Spiegel Brands.”

Spiegel Brands Inc. manages four brands: Spiegel, Newport News, Carabella and A.B. Lambdin which are marketed through separate catalogs and websites. With the addition of a new retail store in King of Prussia, Pennsylvania, the company is today a tri-channel specialty retailer selling numerous products ranging from signature line of luxury fabrics to fashionable clothes, shoes, accessories, swim and travel

goods along with home décor. Spiegel Brands Inc. is part of Catalog Holdings -- Golden Gate Capital's women's apparel holding company.

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Sulzer Pumps Ltd Selects PTC® Product Development System to Improve Global Collaboration

13 May 2008

PTC announced that Sulzer Pumps Ltd., a leading supplier of centrifugal pumps, has chosen PTC's product development system (PDS) to achieve its global product development initiative. After an extensive benchmark against six other leading PLM vendors, Sulzer Pumps Ltd., a division of Switzerland-based Sulzer Group, selected PTC's PDS including Windchill PDMLink®, Windchill ProjectLink™ and ProductView™ for its new global engineering platform. In addition, Sulzer Pumps selected PTC's Global Service Organization (GSO) for consulting and training.

With 5700 employees and nearly 1,3 billion Euro in orders received in 2007, Sulzer Pumps is a leading provider of centrifugal pumping solutions to the oil gas, hydrocarbon, power and water industries as well as to paper and pulp mills industries. Product offerings range from highly sophisticated customer-specific and engineered pumps to highly standardized product series for the pulp and paper segment. Exceptionally fast global growth over recent years has created challenges for Sulzer Pumps around handling complex product configuration and change management processes in a complex CAD environment.

The company decided to implement Windchill to enhance collaboration between new equipment engineering and customer specific support services (CSS) and between distributed manufacturing and assembly sites. Furthermore, the company expects to accelerate time to market, facilitate the reuse of information and improve customer response time and design efficiency. The comprehensive visual collaboration capabilities of ProductView enable global collaboration by providing intuitive access product information at any stage in the development processes and for any team member. Sulzer Pumps plans to implement several hundred seats of Windchill® throughout its globally dispersed engineering, manufacturing and assembly sites. Additionally, PTC's Global Support Organization will provide consulting and implementation support as well as role-based training through PTC University. The global engineering platform is to be integrated with Sulzer Pumps' SAP implementation to allow the interchange of engineering and manufacturing bills of material.

“We conducted a comprehensive three-stage benchmark to find the best out of six PLM vendors for managing dispersed collaboration for our multi-CAD-engineering data and for integrating into our existing ERP-system,” says Dr. Ralf Gerdes, head of research & development at Sulzer Pumps. “Finally, we chose [PTC](#) as we were convinced by the product development system's scalable, web-based software architecture, and PTC's modular implementation approach. As a result of the system's architecture we now have the flexibility to choose the adequate implementation timing for every site. Underscoring all of these points is PTC's expertise in product development and its product development system, which delivers the capabilities we need to meet our business objectives.”

“The market for industrial equipment is undergoing a rapid evolution that is driving the need for competitive differentiation and speed to market. As a result, global players are forced to quickly adapt their business processes to meet ever-changing requirements,” says Dick Harrison, president and CEO, PTC. “Sulzer Pumps' decision to implement the PTC Product Development System underscores the value that PTC solutions offer organizations to unite their enterprise-wide product development

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operations. Windchill's ability to manage heterogeneous product data both inside and outside of Sulzer Pumps disparate locations and divisions supports the organization's business and customer service goals."

[Sulzer](#) prepared the decision for the PLM solution by detailing their product development and engineering processes to determine the specific business requirements and use cases that had to be met. To achieve common understanding, all 13 engineering locations and the product development centres have been involved in the evaluation process. PTC is also recognizing the involvement and support of the senior management team of Sulzer Pumps, to support successful implementation of this globally used PLM solution.

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Synopsys HSIM-XA Adopted by STMicroelectronics for Its Advanced Smart Power Technology

13 May 2008

[Synopsys, Inc.](#) announced the successful outcome of an extensive collaboration with Synopsys HSIM-XA and STMicroelectronics, a global leader in developing and delivering semiconductor solutions across a broad spectrum of microelectronics applications. The result of this joint effort enables ST to significantly accelerate their high-accuracy, transistor level verification of complex analog ICs using ST's Smart Power technology for highly integrated automotive applications.

"Our Smart Power ICs cover a broad spectrum of different applications that continue to grow in complexity. Coupled with wide operating ranges for both voltage and temperature, these designs have posed great challenges for us in the AMS verification domain," said Lyes Djama, AMS Design Platform manager of STMicroelectronics' Smart Power & High Voltage Competence Center. "Using XA technology allows us to significantly improve the AMS verification of these leading-edge designs and meet the challenges we are currently facing."

Synopsys' XA acceleration technology allows customers to achieve HSPICE® accuracy while delivering orders-of-magnitude-higher performance and capacity than existing FastSPICE solutions. XA's superior performance derives from a combination of advanced technologies, including compiled code simulation algorithms for faster transient analysis, topology and behavior-driven recognition algorithms to optimize simulation capacity, and an adaptive multi-rate evaluation engine. When combined with either NanoSim® or HSIM™, XA acceleration technology delivers a complete transistor-level verification solution with higher accuracy and higher throughput.

"Our collaboration with ST on the new XA technology is another example of a mutually beneficial alliance between Synopsys and our customers," said Paul Lo, vice president and general manager of the Analog/Mixed-signal Group at Synopsys, "Combining Synopsys' expertise in circuit simulation and STMicroelectronics' deep knowledge in analog design, we are able to deliver technology that uniquely addresses the requirements of AMS designers. Simply stated, XA technology enables 'out-of-the-box' SPICE accuracy with FastSPICE capacity and performance."

ST's proprietary smart power technology allows analog, digital and power circuits to be integrated on a single chip, producing a complete system - including the MCU - on a single piece of silicon. This exceptional level of integration facilitates more compact packaging and delivers significant benefits to manufacturers of automotive systems through lower costs and increased reliability.

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VISTAGY Partners with 3T to Provide Innovative Composite Bicycle Components

14 May 2008

VISTAGY, Inc. announced a technical partnership with 3T, one of the foremost names in Italian cycling. 3T will use VISTAGY's FiberSIM® software to design, manufacture and optimize the composite components it produces for professional and amateur cyclists. The partnership will provide VISTAGY with valuable insight and experience so it can become an enabling technology in the bicycle components market.

“FiberSIM is the best technology available to engineer composite products, and we believe that's what it takes to produce safety-critical components for world-class athletes,” said Rene Wiertz, president and CEO of 3T. “Our partnership with VISTAGY is further evidence of our commitment to invest in engineering and become the best-in-class component supplier for the bicycle industry.”

3T has entirely renewed its model line—which currently includes stems, drop bars, aero bars, forks and seat posts—to take advantage of the unique properties of composite materials. 3T is investing in the people and tools necessary to design outstanding cycle components, realized with state-of-the-art composite engineering made possible by FiberSIM.

“3T is introducing the same standards of professional engineering to cycling that now exist in aerospace and race car design,” said Richard McAinsh, 3T's technical director. “FiberSIM is critical to that effort and is a key component of our product development platform, which also consists of leading computer-aided-design (CAD) and finite element analysis (FEA) software. These three systems working together give us greater control over manufacturing, significantly increased product quality and reduced time-to-market. We believe this is the new standard for engineering cycle components, and we look forward to working with our colleagues at VISTAGY to raise the bar still further.”

“We're pleased to have the opportunity to partner with a leading manufacturer of bicycle components,” said Steve Luby, president and CEO of VISTAGY. “It will give us a foothold in an exciting new market and enable us to help 3T deliver products of unprecedented quality and sophistication to cycling professionals and enthusiasts.”

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Product News

Bentley Announces Innovative Discovery Subscription Program for GenerativeComponents

15 May 2008

Bentley Systems, Incorporated announced a special new annual subscription program for GenerativeComponents (GC), Bentley's new generative design software for architects and engineers. The GenerativeComponents Discovery Subscription program includes a one-year subscription to GC, plus online learning and support resources to help users accelerate their discovery of the power of this new technology. GC enables architects and engineers to pursue designs and achieve results that were virtually unthinkable before. Empowered by computational methods, designers can direct their creativity to deliver inspired, sustainable buildings that are freer in form and use innovative materials. The GC Discovery Subscription is available to new users for \$250 in the United States. For pricing outside of the U.S., contact Bentley.

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Commenting on this new subscription program, CEO Greg Bentley said, “Thousands have taken advantage of our free trial download of GC that we introduced last year. They have experienced the ability to quickly explore a broad range of ‘what-if’ design alternatives, and their feedback has been most gratifying.

“To empower others to employ computational power through GC to discover their ideal designs, we have developed an extremely cost-effective program. To my knowledge, our Discovery Subscription is the first of its kind among providers of software for infrastructure. We are proud to offer it to architects and engineers around the globe eager to pursue a new approach to design.”

GC uniquely preserves and exploits the critical relationships between design intent and geometry. Users can, for instance, dynamically model and manipulate geometry, apply rules and capture relationships among geometric features, and define complex forms through concisely expressed algorithms. By virtue of GC’s extension of Bentley’s MicroStation environment, the resulting generative designs can flow through to detailed production and fabrication without information loss.

The GC Discovery Subscription is available for secure purchase by credit card online at <http://www.generativecomponents.com>. Along with the software for download, users receive a set of GC-related resources from Bentley – including OnDemand eLearning – and gain entry to the new and expanding BE Communities website, which includes blogs, wikis, forums, and a resource gallery for sharing generative design project work. Practitioners will be able to meet equally inquisitive peers, share how-to information and best practices, and learn about upcoming GC events. You can visit BE Communities, which is still in beta, at community.be.org.

GenerativeComponents is available to Bentley SELECT subscribers at no additional charge. For more information, visit <http://www.generativecomponents.com>.

GC has already been incorporated into the curricula of top architectural and engineering colleges and universities around the world, including Cornell University, the University of Pennsylvania, and MIT in North America; the Bartlett School of Architecture at University College London, the University of Bath, and the Architectural Association in the United Kingdom; TU Delft and KTH Stockholm in Continental Europe; and RMIT University in Australia.

Designs that have been completed using GC include Dostyk Towers by NBBJ and E/Ye Design, Cutty Sark Pavilion by YOUMEHESHE, The Pinnacle by Kohn Pederson Fox, and Museo del Acero by Grimshaw Architects.

About these designs, David Chadwick, editor, CADUser and Construction Computing, said, “Projects already completed using GenerativeComponents clearly illustrate tremendous creativity based on a highly developed sense of intuitive design, while being expressed with a clarity that comes from an equally developed sense of design logic.”

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Bentley AutoPIPE Receives European EN 13480 Approval

14 May 2008

The Swedish inspection authority AF-Kontroll has approved the latest versions of Bentley AutoPIPE in accordance with European EN 13480. The approval enables users who design European Pressure Equipment Directive (PED) certified projects to benefit from the latest Bentley AutoPIPE product enhancements. Other approvals and compliances Bentley AutoPIPE has received include ISO 9001;

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Nuclear NQA-1; 10CFR21; ASME N45.2; GOST approval for oil, gas and power projects in Russia; and Stoomwezen certification by Lloyd's Register Nederland B.V.

Bentley AutoPIPE is a comprehensive and integrated piping analysis and design solution that provides improved productivity and increased interoperability with other computer-aided design (CAD) and analysis software, including STAAD.Pro. It analyzes systems of any complexity and provides special features for buried pipeline analysis, wave loading, water or steam hammer, FRP/GRP pipe, and built-in pipe/structure interaction.

To learn more about Bentley AutoPIPE, visit <http://www.Bentley.com/AutoPIPE>, e-mail structural@bentley.com, or call 1-800-BENTLEY or 610-458-5000.

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Berkeley Design Automation Delivers Over 2x Superior Price/Performance Versus All True SPICE Accurate Circuit Simulators

13 May 2008

[Berkeley Design Automation, Inc.](#) announced the availability of its BDA Token licensing model which provides more than 2x superior price/performance compared to all other true-SPICE-accurate and near-SPICE-accurate circuit simulators – including new “turbo” and “accelerated” SPICE simulators. Several semiconductor companies have already broadly adopted the BDA Token licensing model and are realizing 30% to 40% design cycle reduction.

BDA Token licenses enable capacity on the Analog FastSPICE™ circuit simulator, the RF FastSPICE™ periodic analyzer, and the new Noise Analysis Option™ device noise analyzer. At approximately 2x the price of “golden” SPICE simulators, BDA Tokens deliver 5x-10x higher performance with guaranteed identical waveforms down to the SPICE noise floor. So called “turbo” and “accelerated” SPICE simulators have similar or higher pricing than BDA Tokens, yet typically deliver less than half the performance and may compromise accuracy to do so.

“Our state-of-the-art mobile digital TV applications have extreme verification needs,” said Edward Youssoufian, Director of RF Engineering and Founder, Newport Media, Inc. “BDA Tokens give us the ability to flexibly use Berkeley Design Automation’s true SPICE accuracy, 5x-10x performance, and 5x-10x higher capacity throughout our design cycle and across different types of analysis for complex blocks and full circuits. It is helping us get our leading-edge circuits to market significantly faster and with higher confidence than would otherwise be possible.”

“We entered the market by solving big analog and RF verification problems that were impractical or impossible to solve,” said Ravi Subramanian, president and CEO of Berkeley Design Automation. “Our customers wanted a licensing model that would enable them to fully take advantage of our superior accuracy, 5x-10x performance advantage, and unique functionality throughout their design cycles, while flexibly deploying this functionality across projects. BDA Tokens are the answer.”

Design teams from over 50 companies around the world – from top-10 semiconductor companies to leading startups – use Berkeley Design Automation tools to solve big analog/RF verification problems. Typical applications include characterizing complex blocks (e.g., PLLs, ADCs, DC:DC converters, PHYs, Tx/Rx chains) and running performance simulation of full circuits (e.g., wireless transceivers, wireline transceivers, high-speed I/O macros, memories, microcontrollers, data converters, and power converters).

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Comet Solutions, Inc. Joins Siemens PLM Software Partner Program

14 May 2008

Comet Solutions, Inc. announced its partnership with Siemens PLM Software, a business unit of the Siemens Industry Automation Division.

Comet will provide capability for customers to better automate their design analysis processes and drive product development with engineering intent by the use of highly flexible abstract modeling and custom process simulation templates in an authoring-tool neutral environment for advanced systems engineering and conceptual design analysis.

"This partnership will provide significant value to Siemens PLM Software and Comet customers," said Dan Meyer, president, Comet Solutions. "Siemens PLM Software is a long-term innovator and leader in CAE and their customers are at the forefront of CAE use. We are pleased to provide complementary capabilities that extend the range of conceptual design studies and enable early multi-physics simulation that Siemens PLM Software customers can perform in an NX™-centered environment."

"Comet enables customers to better leverage their existing advanced design, simulation and data management applications - such as those offered by Siemens PLM Software -including their in-house simulation software. By virtue of a unique multi-disciplinary data architecture, Comet enables design engineers as well as CAE analysts to perform complex multi-physics simulation processes through templates that can address optics, thermal, CFD, structural and systems engineering requirements with adaptors to existing commercial CAE software," said Malcolm Panthaki, founder and chief technology officer of Comet Solutions.

In addition to the standard results post-processing and reporting tools available in CAE authoring tools such as the NX Advanced Simulation solution from Siemens PLM Software, Comet's project dashboard provides a flexible, summary view of all the simulation data, easily visible to any level within the organization.

"The engineering-oriented dashboard concisely displays how a design meets product and simulation requirements, regardless of the underlying CAD and CAE tools used, and complements the type of business reporting tools available in PLM systems such as Siemens PLM Software's Teamcenter® portfolio," adds Mr. Panthaki.

"Because Siemens PLM Software is committed to open systems and an open business model, we encourage the integration of third-party software tools that extend an open value proposition to our customers," said Chris Kelley, vice president, Partner & Platform Marketing, Siemens PLM Software. "As a tool-neutral conceptual simulation environment, Comet Solutions fulfills that requirement by embracing and extending the current systems engineering, digital simulation and data management capabilities in Teamcenter, NX and several other Siemens PLM Software solutions such as I-deas®, NX Nastran®, Solid Edge® and Femap®."

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CoWare and Agility Team to Accelerate the Simulation of Complex DSP Algorithms

12 May 2008

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CoWare®, Inc. and [Agility Design Solutions, Inc.](#) announced a strategic relationship focused on accelerating the simulation and implementation of complex DSP algorithms starting from MATLAB models. CoWare is offering its customers integration support for accelerated C models generated by Agility's RMS and MCS products into the entire range of CoWare's ESL 2.0 solutions.

"Many of our customers are developing DSP algorithms starting in MATLAB and later transitioning into CoWare's ESL 2.0 solutions," said Dr. Johannes Stahl, vice president of marketing and business development at CoWare. "With the innovative Agility solutions, we are greatly reducing the transition pain and making the entire flow from MATLAB much more productive."

"Our MATLAB-to-C technology offers a high-productivity, high-performance solution," stated Larry Melling, vice president of marketing at Agility. "We are very excited about the integration with CoWare's ESL design solutions. Working with the leading ESL provider like CoWare will address customers' needs for better connection of their algorithm models with established product development tools."

Unique Advantages of Joint Solution

C models generated from MATLAB will efficiently run inside [CoWare](#) Signal Processing Designer, increasing the simulation performance by more than 3X in typical cases for the entire DSP system explored. This is in comparison to traditional co-simulation running the interpreted MATLAB model using the MATLAB engine. This is relevant in particular in new, complex wireless standards such as the 3GPP Long-Term Evolution (LTE) standard, where many design teams are now transitioning from research in MATLAB to production design efforts.

Complex architectures for consumer applications in the video processing market are developed using CoWare's architecture design solution today. CoWare customers will now be able to take advantage of the Agility technology to include MATLAB models inside virtual hardware platforms modeled in SystemC. A C model generated by Agility's MCS product can be integrated inside CoWare Platform Architect using standard, SystemC interface methodologies.

Availability and Pricing

For general information about the integrated solution, please contact the CoWare sales office nearest you.

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CYA Technologies Announces CYA SmartRecovery and CYA Recycle Bin for the EMC® Documentum® 6 Enterprise Content Management Platform

15 May 2008

CYA Technologies announced CYA SmartRecovery™ 5.0 and CYA Recycle Bin™ version 2.0 supporting the EMC® Documentum® 6 enterprise content management platform.

CYA SmartRecovery is an application-aware, near-CDP solution that protects EMC Documentum repositories against more than 80 percent of all information loss incidents, which result from common occurrences such as programmatic, human, operational and logical errors, malfeasance, and metadata corruption.* Using CYA SmartRecovery, a single administrator can recover one, several, or thousands of documents and their associated metadata (e.g. audit trails, workflows and digital signatures) back to their original state in minutes without taking EMC Documentum offline. CYA SmartRecovery enables

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ECM objects to be recovered back to any point in time, allowing recovery of objects that have been created or modified as little as 15 minutes ago.

CYA Recycle Bin is an “un-delete” tool enabling EMC Documentum end-users to instantly restore files that they have accidentally deleted from the content repository back to their original location. The tool reduces system support costs by eliminating the burden typically placed on IT staff and help desk personnel to manage individual recovery requests.

CYA SmartRecovery and CYA Recycle Bin, previously accredited as “Designed for EMC® Documentum®,” have both been validated on the EMC Documentum 6 platform and have been designated “Documentum 6 Ready” by EMC. Both products are also available for EMC Documentum version 5.3. For more information, visit <http://www.cya.com> or call 203.513.3111 x501.

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DesignAdvance Releases CircuitSpace v2.2 - Unveils New Cross-Probing Technology

12 May 2008

DesignAdvance® Systems, Inc. announced the release of CircuitSpace® v2.2. The new release adds a major new enhancement to CircuitSpace that allows the user to have bi-directional communication between layout and a (PDF) schematic. The new feature gives both Designers and Engineers instant selection and verification of design elements such as components, nets, or pins, within Cadence Allegro and the (PDF) schematic. Through Cross-probing, the user can populate any Cadence Allegro selection set through our proprietary interactive clustering.

Customers have achieved up to 5X returns (2.5 months) on their investment within the first year of using CircuitSpace. Designers reduce board layout and placement time from weeks-to-minutes through CircuitSpace’s patented AutoClustering™, intelligent design (IP) reuse, and Cross-Probing technologies.

“We are impressed with the productivity gains our designers can achieve utilizing CircuitSpace.” stated Mike Brown, PCB Development Manager at Ciena Corporation.

Leading technology companies recognize that reductions in PCB design time have a direct impact on time-to-market for new products, which directly correlates to profitability. “Since the initial release of CircuitSpace, we have worked closely with our customers in developing next generation intelligent EDA solutions for PCB design,” said Edward Pupa, DesignAdvance CEO. “Now with our new Cross-Probing technology, we see CircuitSpace adding value throughout the entire PCB design cycle” continued Pupa.

CircuitSpace Featured Capabilities:

- AutoClustering™
- Bi-directional Cross-Probing between Layout and (PDF) Schematic
- Intelligent physical design reuse and replication
- Concurrent layout development project wide
- Template generation for global library usage across divisions
- Template usage with and without etch
- Automated layout reference designator propagation

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- Advanced sustaining engineering and ECO process
- Automated change report between layout designs

Availability

CircuitSpace v2.2 is now available.

For product pricing information within North America, please visit EMA Design Automation at <http://www.ema-eda.com>

For product pricing information outside of North America, please visit our distribution partners at <http://www.designadvance.com>

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Edgcam 12.5 Improves Automation of NC Programming and Increases User Control

1 May 2008

The improvements in Edgcam Part Modeler include thread features and additional attributes for Hole features that are passed to Edgcam for use in the manufacturing process.

Edgcam enables automatic model alignment and one shot feature finding for all milling and turning models and provides enhanced chuck jaw and chuck setup options for greater machine tool set-up flexibility and improved collision detection.

Latest enhancements in Strategy Manager for Mill/Turn make additional data available to users, capturing customers knowledge and proven processes to be applied to multiple jobs, thereby saving time and reducing costs.

Edgcam's feature browser gives Solid Machinist users greater control over the machining order, making it easier to view which tools and cycles have been applied to a feature. In addition, the manufacturing sequence can be easily sorted by feature type or manufacturing method and is controlled using simple drag and drop techniques.

The new rough turning cycle includes improved chip control reducing notching and tool wear. A choice of toolpath control options allows the most effective process to be applied to the turned component.

Edgcam 12.5 further expands the applications established 4/5-axis simultaneous machining strategies by offering support for Pro/ENGINEER & Wildfire CAD models.

Additional options to control how the part is positioned and machined along with a Cusp Height control option, are also included.

Enhancements based on customer feedback include improved sequence regeneration performance when editing non-toolpath information, canned hole cycles supported in rotary transformations, editing of the lathe setup, helical profiling with cutter radius compensation and the ability to explode grouped hole features.

The latest version of Edgcam also supports the latest Solid CAD Modelers including Autodesk Inventor, SolidWorks, Solid Edge, Unigraphics, Pro/ENGINEER and CATIA.

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EMC Empowers Broad Range of Organizations to Reap the Benefits of XML

13 May 2008

EMC Corporation unveiled two new EMC Documentum products designed to bring the power of XML (eXtensible Markup Language) technology to a broader range of enterprise information. EMC Documentum XML Store and Documentum Dynamic Delivery Services represent an important milestone in EMC's expanded commitment to XML as the underpinning for a variety of content formats, as well as the technology that facilitates convergence of structured and unstructured information.

Leading today's announcement is EMC Documentum XML Store, a new native XML repository that integrates into the Documentum platform to provide fast and scalable XML processing. Unlike other enterprise content management (ECM) products and XML point solutions, the Documentum repository gives organizations a full range of ECM management for their XML content, along with new capabilities for granular content reuse, standards-based search/retrieval, dynamic publishing, and archiving.

Documentum XML Store is the foundation for the second product announced today, EMC Documentum Dynamic Delivery Services. This server-based content delivery technology improves the way XML can be delivered dynamically to various applications. With Documentum Dynamic Delivery Services, organizations can transform traditional content publishing from a static activity to an on-demand process where personalized, relevant content is delivered to users based on their specific requests, preferences and profiles.

As XML has become the de facto standard for representing all types of information, many organizations have adopted it as a self-describing data format that enables application integration, improves information access, enables repurposed content and satisfies record retention requirements. With the addition of Documentum XML Store to the Documentum enterprise content management platform, XML can now be a driver for any type of content-rich application using office documents, blogs, wikis, RSS feeds, mash-ups, business processes, or messages..

"Customers today face a tremendous challenge in effectively harnessing their unstructured information – the very content that drives a majority of business processes," said Balaji Yelamanchili, Senior Vice President and General Manager, EMC Content Management and Archiving. "With these announcements, EMC now provides the market's very best ECM capabilities for XML content -- offering a powerful, standards-based XML information repository within an enterprise content management system. The end result is an integrated, end-to-end solution for creating, managing, accessing, archiving, and delivering XML alongside all forms of enterprise information."

Documentum Dynamic Delivery Services embeds XML Store to aggregate and cache content from any number of source systems. Documentum XML Store's full text engine and one of the industry's fastest XQuery engines combine to support search and retrieval of any type of content. Output documents are dynamically constructed from content fragments, and Documentum Dynamic Delivery Services' scalable architecture allows it to serve high volumes of personalized requests.

EMC's Documentum XML Store and Documentum Dynamic Delivery Services are available now. More information on EMC's content management products can be found at

<http://www.emc.com/products/category/content-management.htm>

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Enterprise Informatics Releases eB Nuclear Performance Improvement

8 May 2008

Enterprise Informatics announced the availability of eB Nuclear Performance Improvement – a integrated suite of tools that automate the processes and procedures for performance improvement defined by the Institute of Nuclear Power Operations (INPO) Guidelines for Performance Improvement at Nuclear Power Stations©.

eB Performance Improvement is a single integrated platform for the management of Condition reports, Corrective actions, Preventative actions, Operating Experience (both incoming and outgoing), Observations (online surveys), Benchmarking and Self Assessment. The solution integrates eB Corrective Action and eB Human Performance features that adhere to the Performance Improvement Guidelines defined by INPO 05-005©.

eB Performance Improvement is currently in full production as a Fleet solution at Constellation Energy’s headquarters and the R.E. Ginna Nuclear power plant with additional deployments in process at Calvert Cliffs and Nine Mile Point. Ginna has transitioned from a fragmented collection of performance improvement sub-elements to a fully integrated process that meets/exceeds INPO Performance Improvement Guidelines.

“Constellation Energy selected the Enterprise Informatics eB Nuclear solution for our Fleetwide e-PIC (electronic Performance Improvement Center) because they offer unparalleled knowledge and commitment to the Nuclear market and a fully integrated suite of Nuclear specific applications that implement industry best practices”, said Gerry Doyle, Director Fleet Performance Improvement, Constellation Energy.

“eB Corrective Action automates and facilitates identifying and resolving Conditions Adverse to Quality issues and incidents through user-friendly condition reports, reviews and action tracking. Automated workflows, based on industry best practices, streamline the Performance Improvement process, lowering risk of non-compliance while improving the efficiency of plant operations.

eB Human Performance automates processes for conducting observations, self assessments, benchmarks, and operating experience. Together, eB Corrective Action and eB Human Performance enable organizations to effectively manage the performance improvement process and automate the methodology for successfully implementing and achieving excellence in safety and performance. eB Performance Improvement is a cornerstone application to the eB Nuclear solution which offers a specific suite of applications for Design Engineering, Information Management and Compliance.

A comprehensive overview and live demonstration of eB Performance Improvement is available in a free, 1 hour on-demand [webinar](#). A Constellation Energy customer case study is under development and will be available in the next few weeks.

For information about eB Nuclear, visit <http://www.enterpriseinformatics.com/nuclear.shtml>.

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Flomerics EFD.Lab Simulation Software for Autodesk© Inventor© Users Offers Enhanced Usability and Increased Performance

15 May 2008

Flomerics Ltd. announced the availability of version 8.2 of EFD.Lab, its Engineering Fluid Dynamics

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(EFD) fluid flow and thermal simulation tool for Autodesk Inventor users. EFD is based on the same mathematical principles of Computational Fluid Dynamics (CFD) but it is also easier and faster to use for mechanical engineers. EFD.Lab 8.2 offers improved usability as well as increased performance. "CFD is an important component of virtual prototyping" said Ivo Weinhold, the engineering fluid dynamics business manager at Flomerics. "EFD.Lab ensures easy access of technology to Inventor users at the right time during the design process so virtual prototyping can become a reality."

Among the most salient features of version 8.2 are:

- EFD.Lab recognizes features and parameters on imported geometries from Autodesk Inventor. Therefore, users maintain all the benefits of parametric-based solid modeling and can easily modify geometry parameters to take advantage of effortless "what-if" testing.
- EFD.Lab features an optimized mesher which requires even less RAM to solve models with a large number of features. As a result, more complicated models with a large number of components can be solved effortlessly with EFD.Lab.
- Additional functionalities have been added in support of electronics applications. For example, the perforated plates function has been further improved to support holes with arbitrary shapes. As a result, users can analyze even more complex perforated plates without manual intervention.

EFD.Lab 8.2 is available for immediate shipment. Interested readers may watch a short online EFD.Lab demo for free at <http://www.flomerics.com/products/efdlab/demo.php>.

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Magma's FineSim SPICE Circuit Simulator Qualifies Designs Targeting for TSMC's 40- and 65-Nanometer Process Technologies

15 May 2008

Magma® Design Automation Inc. announced that TSMC qualified the accuracy and performance of Magma's FineSim™ SPICE for designs targeting TSMC's 65- and 40-nanometer (nm) processes.

Magma is one of the first electronic design automation companies to participate in the TSMC SPICE Tool Qualification Program. FineSim SPICE supports the program's interoperable SPICE Design Kit (iSDK) and Magma has adopted the TSMC Model Interface (TMI). Through early tool qualification and support of this program, Magma provides greater accuracy and higher performance SPICE simulation.

"Magma's new technology correlates with our 65- and 40-nm processes," said S. T. Juang, senior director of Design Infrastructure Marketing, TSMC. "FineSim SPICE met our requirements for accuracy and performance."

"By completing TSMC's rigorous qualification process, Magma ensures that designers will be able to leverage FineSim SPICE and its unique Native Parallel Technology™ to shorten simulation run time," said Suk Lee, general manager of Magma's Custom Design Business Unit. "Now designers can have increased confidence in their ability to verify their most challenging analog designs."

TSMC has prepared a qualification report on FineSim SPICE.

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Operation Technology, Inc. – ETAP® Joins Intergraph® SmartPlant® Alliance Program

13 May 2008

Operation Technology Inc. (OTI), developers and designers of the ETAP® enterprise solution for electrical power systems, has joined the Intergraph® SmartPlant® alliance program. Using OTI's ETAP software analysis platform together with Intergraph's SmartPlant Electrical solution, the combined interface allows for the design and validation of power distribution systems prior to delivery and installation, promoting higher quality, greater reliability and safer designs in less time.

ETAP is the most comprehensive analysis platform for the design, simulation, operation, control, optimization and automation of generation, transmission, distribution and industrial power systems. ETAP offers a suite of fully integrated software solutions including arc flash, load flow, short circuit, relay coordination, cable ampacity, transient stability, optimal power flow and more. Its modular functionality can be tailored to fit the needs of any company, from small to large power systems.

SmartPlant Electrical addresses the electrical needs of the entire life cycle of the plant, from concept to detailed design through operations and maintenance, including start-up, continuous operation, emergencies and shutdowns. It generates single-line diagrams and schematics automatically, creating graphical reports based on data provided by the engineers.

Together, SmartPlant Electrical and ETAP provide a total engineering solution where the power distribution system is designed with SmartPlant Electrical, interfaced to ETAP for validation and verification, and then imported back for updates as required to create the deliverable system for owner operators and engineering, procurement and construction (EPC) firms. This solution is viable for all areas of the process, power (including nuclear for which ETAP is fully certified), and marine industries that require power distribution designs.

"Some of the largest design firms, power utilities, nuclear power plants, and government agencies are [ETAP](#) and SmartPlant Electric users and they need an easy and intelligent way to transfer design and analysis process across their organizations, regardless of location or solution platform," said Farrokh Shokooh, president and CEO of OTI. "Our participation in Intergraph SmartPlant Alliance program means offering a unified electrical design solution – delivering to our customers a higher-quality user experience, with greater reliability and lower total cost of ownership."

"We are pleased OTI has joined our SmartPlant Alliance program to provide our mutual users additional electrical design capabilities," said Patrick Holcomb, executive vice president, [Intergraph](#) Process, Power and Marine. "The functionality of our SmartPlant Electrical solution, combined with ETAP, provides a superior offering for owner operators and the EPC companies that design and construct industrial power systems. We look forward to building on this relationship to continue to provide even better solutions in the future," he said.

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Revit Architecture and Autodesk 3ds Max Design Software Accelerate the Building Design Process

13 May 2008

At the VisMasters Design, Modeling and Visualization Conference, Autodesk, Inc. highlighted how architects around the world are adopting Revit Architecture software for building information modeling (BIM) and [Autodesk](#) 3ds Max Design software for 3D visualization. Over 300,000 architects, designers and engineers have moved to building information modeling by adopting the Revit platform for BIM.

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SHoP Architects and Archaus Architects are among the firms reaping the benefits of a Revit Architecture and 3ds Max Design workflow.

The powerful combination of Revit Architecture and 3ds Max Design enables designers to more fully leverage the power of BIM across their processes. Used together, the products also ease the aggregation of additional scene elements, provide advanced texturing and modeling tools for quick iterations of rendered images, and allow designers to animate objects or add special effects to tell the complete story of their designs.

SHoP Architects

New York-based SHoP Architects first implemented Revit Architecture into its workflow for the 290 Mulberry project. Both Revit Architecture and 3ds Max were used to design and promote the 13-story building, which will be located in New York.

In the preliminary stages of the project, 3ds Max was used for pre-schematic and conceptual design. All aspects of the drawing set were created in Revit Architecture, including the design documents and construction documents. SHoP later relied on 3ds Max to produce photo real renderings, which were used to market the project. The Revit model is currently being used for construction coordination, and SHoP has a daily presence on-site to facilitate the use of the model.

David Fano, director of technology research at the firm noted, "Much of what architects do is dependent on deliverables. Using Revit Architecture and 3ds Max in tandem significantly reduced the time and effort that went into all aspects of the project. It was much easier to manage the drawing set through Revit Architecture, as the software allowed us to focus on the building and worry less about important yet mundane issues. 3ds Max was also great in that it gave us the ability to quickly and loosely model and render elements of the building throughout the design process."

Archaus Architects

New Zealand-based Archaus Architects have used Revit Architecture and 3ds Max to complete over 30 projects from design through to construction documentation, and are currently relying on the solutions for another 20 projects in development. These include the landmark development 'Zone One', a new 270,000 square foot mixed-use development in the New Zealand capital of Wellington.

"The use of Revit Architecture and 3ds Max on this project allowed us to analyze and test various design options quickly and easily," said Erin Collins, project architect for Archaus Architects. "Grouped components and referenced linked files were used extensively for each of the modular units both in Revit Architecture and 3ds Max. This allowed us to make design changes and update the model within minutes."

Collins adds, "Revit Architecture software's shaded 3D camera views and traditional 2D drafting views were used alongside highly detailed photorealistic renderings created in 3ds Max to more effectively communicate our design ideas and visions for the project. When it came time to move the conceptual digital 'sketches' into high resolution photorealistic marketing images, our client was blown away by the quality of the material we provided, and the short timeframe in which Revit Architecture and 3ds Max allowed us to produce them."

About Autodesk 3ds Max Design

Autodesk 3ds Max Design is the latest version of 3ds Max software that is specifically tailored to the needs of architects, designers, and visualization specialists. It allows them to explore, validate, and

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communicate their designs with impact, from early concept models to fully animated, cinema-quality presentations.

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Right Hemisphere Transfers Deep Creator Product Development to Esperient Corporation

12 May 2008

Right Hemisphere® announced that it has signed an agreement with Esperient Corporation to outsource the development, maintenance and customer support of its Deep Creator™ 3D authoring software. Esperient has already assumed sales and support responsibilities for Deep Creator and its customers, and has developed a new 3.0 version of the software available today through its e-store. As part of the agreement, Right Hemisphere will retain its interest in Deep Creator by becoming a shareholder in Esperient and by ensuring the product's tight integration with Right Hemisphere's enterprise solutions. Right Hemisphere will also continue to sell Deep Creator to its Deep Server™ enterprise customers.

Esperient was founded in October 2007 by four former Right Hemisphere employees with a distinct passion for interactive 3D visualization and simulation technology. The Esperient technical team is headed by Michael Bailey, the original architect of Deep Creator.

"All Right Hemisphere customers will be better served by this agreement with Esperient," said Michael Lynch, CEO at Right Hemisphere. "With Deep Creator back in the hands of its original development team and visionary leader, the product will move forward much faster. At the same time, our core engineering team will be able sharpen its focus on advancing our graphics management and publishing solutions. This is the classic win-win."

Announcing Esperient Creator 3.0

[Right Hemisphere](#) and Esperient began their collaboration last October when the two companies signed an Interim Licensing Agreement. Since then, Esperient has been reviewing customer feedback and incorporating that feedback into its development of a new major release of the product. The new release -- formally renamed Esperient Creator 3.0 -- is available starting today and has more than 200 new features.

Esperient Creator 3.0 software now delivers:

- A streamlined user interface.
- Improved support for designers working on very large resolution, multi-screen based authoring.
- A completely revamped in-built asset browser with new support for interactive 3D material previews and drag and drop scene authoring for applying materials, meshes and objects to an interactive 3D scene.
- Industry-leading render to texture support, including advanced real-time water with real-time reflection and refraction effects as well as real-time shadow maps and over 100 pre-built pixel and vertex shaders.
- Extended video support so users can include streaming media in interactive 3D scenes using popular video formats such as Apple QuickTime (.mov), Microsoft® Windows Media® Video (wmv) and Adobe® Flash® Video (.flv).
- Support for the latest Right Hemisphere importers such as Autodesk® 3ds Max® 2008, Autodesk® Maya® 2008, and Google SketchUp 6.

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Esperient Creator 3.0 is available for purchase and download from the Esperient Web site at <http://www.esperient.com>. Esperient has also established a new Creator user forum on its Web site.

CEO of Esperient Ben Vaughan said, "We are delighted to have signed this agreement with Right Hemisphere and extremely pleased that they have decided to maintain a long term interest in Esperient. We have exciting plans for the future development of Esperient Creator. In part, this is reflected in our decision to change the license terms to an annual subscription and to reduce the cost of the product to just \$500."

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SAP and TechniData Release Market's Most Comprehensive Solution for Achieving EU Chemical Regulation Compliance

15 May 2008

SAP AG and TechniData AG, the SAP development partner for environmental compliance solutions, announced the availability of SAP® REACH Compliance. The first REACH compliance deadline is pre-registration, which runs from June 1, 2008 to November 30, 2008. The remaining three REACH deadlines will occur in 2010, 2013 and 2018, respectively.

During the first several years under REACH, the average chemical company is estimated to handle 15,000 compliance projects, each involving substance registration, usage and management, supply chain, financial and legal processes. REACH places the burden of proving the safety of chemical substances, products and consumer use on the manufacturer and importer. Chemical, consumer product, mill, oil and gas, pharmaceutical and other process manufactures will be denied the right to trade non-compliant substances within the European Union (EU).

Clariant, a global leader in the field of specialty chemicals, aggressively implemented of SAP REACH Compliance months before the first legislative deadline.

"From day one, Clariant will enjoy a competitive advantage under compliance, with the unique ability to manage all aspects of mandated data via a single software application," said Dr. Uwe Wolfmeier, Head of Corporate Product Safety, Clariant. "The level of enterprise-wide execution demanded by REACH is simply too complex to trust to disparate point applications, let alone ones that don't integrate with a company's existing core business processes."

Despite the potential for significant business disruptions and revenue losses related to non-compliance, a recent PricewaterhouseCoopers survey indicates that many chemical companies are expected to miss the 2008 REACH deadline. Companies are underestimating the level of enterprise-wide coordination, and remain uncertain about the type of technology commitment required to achieve compliance.

"Companies have recognized the importance and the necessity of IT support for REACH" said Jürgen Schwab, CEO, TechniData. "Reach will be an ongoing task, not only an activity for 2008. Companies that set up the right REACH IT infrastructure today will avoid an ongoing struggle with insufficient tools in the future."

SAP REACH Compliance integrates with companies' existing enterprise resource planning, supply chain management and SAP® Environment, Health & Safety applications. The solution from SAP and TechniData also supports third-party software for authoring chemical-safety assessments, chemical-safety reports and standard EU REACH exchange formats, such as the IUCLID 5 solution.

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Key functionalities of SAP REACH Compliance include:

Substance and Usage Management

- Manage data and track chemicals used in particular preparations, products and requisite documents, including chemical-safety assessments, chemical-safety reports and enhanced material-safety data sheets.
- Evaluate current REACH status, track quantities of single substances for a single legal entity or monitor substances on a corporate level covering multiple legal entities, and identify and rectify any compliance gaps.

Supply Chain Collaboration

- Electronic information exchange of processes involved in REACH-related supply chain communication, supported by material-safety data sheets and questionnaire-based communication for use and exposure scenarios.
- Supplier and customer communication data tracking, including how customers use a product in order to draw up exposure scenarios for substances, and initiate follow-up activities based on deadlines and business-partner responses.

Legal Process Management for REACH

- Organize and monitor all authority-related processes, including registration, notification and authorization.
- Collaborate document management between internal and external groups to expedite registration management, keeping business processes transparent, reliable and viewable in real-time.
- Plan on detailed substance and full substance-portfolio management levels to control costs, coordinate activities and successfully register substances and receive authorization with REACH authorities.

“Providing a single integrated solution for all REACH regulatory needs significantly reduces companies’ compliance costs and implementation times,” said Franz Hero, vice president, Chemicals, SAP AG. “With global competition and economic pressures increasing exponentially, companies cannot afford to slow down for regulatory business disruptions. SAP REACH Compliance enables companies to forge ahead at full throttle, without having to make pit stops to change regulatory tires.”

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Synergis Engineering Design Solutions Authorized to Sell Autodesk Industrial Design Solutions

13 May 2008

The Synergis Engineering Design Solutions Division of Synergis Technologies, Inc. announced that it has been authorized to sell and support Autodesk's industrial design solutions, such as Autodesk AliasStudio and Autodesk Showcase software, to customers in the Mid-Atlantic region. These industrial design solutions give Synergis Engineering Design Solutions' manufacturing customers a complete set of tools that makes it even easier to fully transition to digital prototyping-enabling manufacturing workgroups to create a single digital model that can be used in every stage of production, from conceptual design to manufacturing.

With Autodesk AliasStudio, users can iterate on designs faster, visually collaborate, and convey their

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vision to develop new product designs in less time-and at a lower cost. And, with Autodesk Showcase software, users have all the tools they need to create accurate, photo realistic product representations from 3D CAD data models so users can clearly communicate their consumer product intentions and facilitate more informed decision-making. Both applications allow users to keep designs digital for a longer period and bring products to market more efficiently.

With Synergis Engineering Design Solutions' and Autodesk's help, Viking Yachts purchased and has begun to incorporate these state-of-the-art industrial design solutions into their business. Adopting Alias enables them to stay on the forefront of technology and visualize, simulate and analyze their designs early in the design process to save time and money, enhance quality and foster innovation.

"The training and support we have received from Synergis Engineering Design Solutions has been critical to our successful adoption of Autodesk software. They've definitely been there for us as we acquire new software and push its limitations. We have a strong, mutually beneficial partnership that has stood the test of time," said Kurt Bender, CAD manager, Viking Yachts. "More than ever, Synergis' support is a requirement. We're on the horn with them regularly and we lean on them for help and troubleshooting as necessary. When the transition is complete, we'll be capturing all of our ideas digitally and never have to worry again that our creativity gets lost between napkin sketches and our 3D software."

"By keeping designs in a digital format longer, manufacturers can virtually explore their product, complete with all of its options, and simulate real-world performance before it is ever built," said Jennifer Zavacky, sales and marketing director for the Manufacturing Solutions Division at [Synergis Engineering Design Solutions](#). "We're excited about bringing these solutions to our customers, partnering with them in their move toward digital prototyping, and helping them reduce their reliance on costly prototypes."

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Synopsys Adds 30 New Titles to DesignWare System-Level Library

15 May 2008

Synopsys, Inc. announced the immediate availability of 30 new titles in the DesignWare® System-Level Library. The new members of the Library include high-performance transaction-level models (TLMs) for PowerPC®, MIPS, and [DesignWare IP](#). DesignWare System-Level Library models significantly reduce the time to create virtual platforms and are written in SystemC to work in any IEEE 1666 (SystemC)-compliant simulation environment.

Virtual platforms are fast, full-function simulation models of hardware that enable development and integration of software months before hardware is available. Transaction-level models (TLM) are the basic building blocks required to build virtual platforms for early software development, hardware/software co-design, architectural exploration and system verification. The DesignWare System-Level Library is the industry's most comprehensive portfolio of tool-independent, standards-based TLMs, a primary reason that IBM selected Synopsys for distribution of its SystemC-based PowerPC models.

"Synopsys' market position in the IP space made the DesignWare System- Level Library a natural choice to distribute our processor models," said Mike McGinnis, IBM's program director for PowerPC licensing. "Open standards are crucial to enable growth of a broader system-level ecosystem, and our mutual customers will benefit from the tool-independence of our SystemC models."

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The DesignWare System-Level Library now features more than 80 TLMs. New high-performance models of the PowerPC 405, 440, and 460 and MIPS 4Kc complement the Library's existing models of ARM® processors. In addition, TLMs for Synopsys' DesignWare PCI Express 2.0 and Gigabit Ethernet Media Access Controller (GMAC) join other DesignWare IP, such as USB 2.0 HS OTG, SATA AHCI and AMBA® interconnect components, in the Library. Several peripheral components include Virtual I/O capability, which allows communication over the host Ethernet or USB connection of the computer executing the virtual platform. Also included are pre-assembled models of complete PowerPC and MIPS 4Kc platforms which can be used as reference designs for driver development or as a starting point for building larger virtual platforms.

Synopsys will showcase the DesignWare System-Level Library and its Innovator virtual platform development tools as a Gold Sponsor at the upcoming Power Architecture Conference (<http://www.power.org/events/powercon/>) being held in Munich and Paris during May 2008. The solutions will also be exhibited at the Design Automation Conference in Anaheim in June.

"IBM's choice of the DesignWare System-Level Library as a distribution vehicle for their PowerPC models builds additional value into the Library and we look forward to including models from more partners in the future," said John Koeter, senior director of marketing for IP and Services at Synopsys. "With the upcoming ratification of the SystemC TLM-2.0 standard and our DesignWare System-Level Library's compliance with TLM-2.0, we can help to ensure model interoperability for the creation of virtual platforms to accelerate software development. It makes adopting Synopsys' broad array of popular IP titles a safe investment for our customers."

Availability

The new titles, including the instruction-accurate MIPS 4Kc and cycle-accurate PowerPC 405, 440, and 460 transaction-level models, are available now. The instruction-accurate PowerPC transaction-level models will be available in June. For more information, visit <http://www.designware.com/sll>.

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The MathWorks Simplifies Development of Parallel Applications in MATLAB

12 May 2008

[The MathWorks](#) announced the integration of its [Parallel Computing Toolbox](#) with its [MATLAB](#) optimization toolboxes to help further simplify the development of parallel applications. Parallel computing capabilities are now integrated inside the optimization solvers of MathWorks [Optimization Toolbox](#) and [Genetic Algorithm and Direct Search Toolbox](#), enabling users to solve computationally-intensive optimization problems on multicore computers and computer clusters without significantly changing their existing programs.

The MathWorks optimization toolboxes give engineers and scientists the tools needed to find optimal solutions, perform tradeoff analysis, balance multiple design alternatives, and incorporate optimization methods in their algorithms and models. The integration of select optimization solvers with Parallel Computing Toolbox allows for the use of available computational resources to solve more computationally-intensive problems than previously possible on a single core. The result is a reduction in the time to solution for optimization problems that are amenable to parallel computing. Example applications include calibrating an automotive engine control unit with experimental data, identifying an aircraft design that minimizes noise while maximizing fuel efficiency and selecting a portfolio of stocks that maximize gains while minimizing risk.

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“This latest announcement demonstrates our company’s continued commitment to helping the industry overcome the challenges associated with development of parallel applications,” said Silvina Grad-Freilich, manager of parallel computing and application deployment marketing of The MathWorks. “The parallel computing capabilities provided within our toolboxes allow MATLAB users to develop parallel applications using exactly the same functions that they use in their serial programs, empowering engineers and scientists to experience the benefits of high-performance computing without necessitating that they learn new skill sets.”

Additional features with this release include support for two additional widely used schedulers in the Parallel Computing Toolbox: PBS Pro from Altair Grid Technologies and TORQUE. Support for third-party schedulers enable cluster administrators to integrate MathWorks parallel computing tools into their existing distributed computing environments.

About Parallel Computing Toolbox

Parallel Computing Toolbox offers features that simplify the development of parallel applications in MATLAB, including programming constructs such as parallel for-loops and distributed arrays that let users harness multicore and multiprocessor hardware environments. These constructs can be used without learning a complex parallel language or making significant changes to existing serial code. For further information, please visit the product Web site at: <http://www.mathworks.com/products/distribtb/>

About Optimization Toolbox

Optimization Toolbox extends the MATLAB technical computing environment with tools and widely used algorithms for standard and large-scale optimization. These algorithms solve constrained and unconstrained continuous and discrete problems. The toolbox includes functions for linear programming, quadratic programming, nonlinear optimization, nonlinear least squares, solving systems of nonlinear equations, multi-objective optimization, and binary integer programming. For further information, please visit the product Web site at: <http://www.mathworks.com/products/optimization/>

About Genetic Algorithm and Direct Search Toolbox

Genetic Algorithm and Direct Search Toolbox software extends the optimization capabilities in MATLAB and Optimization Toolbox products with tools for using genetic algorithms, simulated annealing, and direct search. These algorithms can be used for problems that are difficult to solve with traditional optimization techniques, including problems that are not well defined or are difficult to model mathematically. For further information, please visit the product Web site at: <http://www.mathworks.com/products/gads>.

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think3 Hits the Market with New Suite of CAD and PLM Solutions 2008.1

9 May 2008

think3 has launched new release of its CAD and PLM product lines ThinkDesign Suite and thinkPLM Suite 2008.1.

ThinkDesign Suite streamlines think3’s offering of CAD solutions by aggregating a host of functionalities into four main product lines: ThinkDesign Engineering for mechanical engineers; ThinkDesign Tooling for toolmakers and technicians; ThinkDesign Styling for design specialists and ThinkDesign Professional which brings together all think3 technology functionalities into a single

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solution.

In addition, the Italian based software company with operations in Europe, USA, Japan and India, has announced new developments in think3's offer of Product Lifecycle Management solutions. thinkPLM Suite now offers full integration capabilities with Outlook and Solid Edge, and includes a completely revised version of the WebTeam application, which now enables users to upload information on to thinkteam databases remotely.

ThinkDesign Suite

ThinkDesign Suite 2008.1 introduces improvements in all product areas, including enhancements to layer and workplane management functionalities, vertical functions for dies and a more powerful drawing environment to make detailing operations faster. The Renderer has been completely revised to make it more powerful and user friendly and the functions originally contained in the thinkreal module are now incorporated into the Professional, Engineering and Styling foundations. Moreover, the graphic interface has been improved while static and dynamic rendering settings have been unified. The newly launched suite also features enhanced Interactive Solid Modeling (ISM) functionalities.

Major developments in ThinkDesign Engineering solutions include the new Tubing module featuring a set of capabilities that help define tube structures. This allows users to design a tubing system, and automatically insert connectors at shared intersections and T joints, once a 3D path has been defined.

The X-Camme application allows for better flat and cylindrical cams design process. The improved interaction between think3 graphic interface and the Microsoft Excel based calculation engine, makes it easier to process and automatically generate both 3D models and all parameters needed to produce cams.

ThinkDesign Tooling features key improvements to the Compensator functions and offers a powerful solution to calculate metal sheet spined twist compensation. Enhancements include improved mesh loading, calculation, checking and curve extraction capabilities that ensure better performance and optimised results.

The Die Design module offers new features that allow for better cutting line definition and compensation of local and targeted GSM spined twist.

ThinkDesign Styling offers significant developments to the Rake-Sweep capability, which enable users to select a set of surfaces to be uniquely used as a second guide. Customers can select one or both sides where the surface will be generated, if the section is not positioned on one end of the first guide. Moreover, the new Rotational Sweep allows for the creation of rotational sweep surfaces by rotating a set of sections around an axis, which can be specified directly by the user or selected by default by the program. Optionally, users can select a set of guide curves that the rotational surfaces will follow. Autointersections are now detected and indicated by a special message.

ThinkDesign Suite now also offers ThinkDesign Modifier, a stand-alone solution designed to modify solids and surfaces imported from other CAD systems using GSM (Global Shape Modeling) and ISM (Interactive Solid Modeling).

thinkPLM Suite

[Think3](#)'s Product Lifecycle Management suite now allows for full integration with Microsoft's e-mail management program Outlook. Its integration into thinkteam database joins the other Microsoft Office applications (Word, Excel, PowerPoint) already supported by the PLM program. As a result, all e-mails that refer to a specific activity or order can be now archived in the thinkteam database together with all

information needed to facilitate search and process management.

The WebTeam application enables users to access a remote thinkteam database, as well as download and upload information from a remote database. The program has been completely revamped and now boasts an innovative “task driven” interface which makes it even easier to use.

Solid Edge now joins the wide range of CAD products supported and integrated into thinkPLM Suite. Users of these modelling products can now enjoy the enormous benefits of this PLM solution from think3.

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UMC and Mentor Graphics Introduce Foundry Design Kits (FDK) for Mixed-Mode and RF Technologies

13 May 2008

UMC and Mentor Graphics Corporation announced they have partnered to offer a new series of analog/mixed-signal and RF foundry design kits (FDKs). The FDKs, containing comprehensive and validated building blocks at the transistor device level, help IC designers to jump-start design cycles on UMC’s 0.13um and 90nm MM/RF process nodes. Featuring Mentor’s analog/mixed-signal IC flow, the FDKs are poised to reduce time-to-market and optimize manufacturing success for analog, mixed mode and RF system-on-chip (SoC) ICs.

“Mentor’s FDKs for UMC’s advanced MM/RF process provide our customers with key technology to help them achieve first silicon success,” said Lee Chung, vice president of global marketing at UMC. “Since the FDKs are validated within Mentor’s complete mixed-signal SoC design flow, customers can gain competitive time-to-manufacturing advantages with the assurances of a proven, turn-key methodology and a proven path to silicon.”

The comprehensive FDKs include UMC Eldo simulation models, Calibre DRC, LVS and extraction technology files, schematic symbols and programmable device generators for supporting schematic driven layout and simulation, along with a set of configuration files for customization.

“We are pleased to partner with [UMC](#) to offer this comprehensive set of FDKs,” noted Jue-Hsien Chern, vice president of DSM at Mentor Graphics. “The combination of UMC’s production-proven, mixed-signal and RF processes and Mentor’s world-class, optimized mixed-signal design flow will enable our mutual customers to have optimal control and predictability over their SoC design and manufacturing.”

UMC's mainstream 0.13um process employs up to 8 layers of copper interconnects to enable a gate density of 220K gates/mm². UMC’s 90nm process has been in customer production since March of 2003, making UMC the first dedicated foundry company to announce the delivery of working customer ICs built on this technology node. UMC and [Mentor Graphics](#) will continue to extend FDK offerings to 65nm and beyond by leveraging Mentor’s IC flow, which contains a unified design platform with a centralized design cockpit that allows seamless navigation throughout the entire analog mixed-signal IC design flow, from schematic capture, simulation and floor planning, to physical layout and final verification.

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VeriSilicon Joins Power Forward Initiative to Accelerate Advanced Low-Power Design

12 May 2008

VeriSilicon Holdings Co., Ltd. (VeriSilicon) has joined the Power Forward Initiative (PFI) and plans to offer a Common Power Format (CPF)-based design solution for its ASIC customers.

[VeriSilicon](#) uses the Cadence® Design Systems, Inc. Low-Power Solution.

"Low-power design is critical for multimedia, wireless and communication applications," said Nianfeng Li, corporate vice president of Design Methodologies at VeriSilicon. "We have joined the Power Forward Initiative to contribute our low-power expertise in support of the broad, industry-wide move to low-power electronic design. VeriSilicon has worked with Cadence to deploy this advanced low-power solution for our ASIC customers. We expect that CPF will streamline the entire low-power design process to help customers meet their market requirements on time."

"VeriSilicon, with its focus on the fast growing market in China, brings a unique perspective to the Power Forward Initiative. Their participation will help accelerate the use of low-power technologies in the industry," said Pankaj Mayor, group director of Business Enablement at Cadence. "We applaud VeriSilicon's commitment and investment of resources to support the Power Forward Initiative and look forward to their participation."

CPF, an Si2-approved standard format, is used for specifying power-saving techniques early in the design process -- enabling sharing and reuse of low-power intelligence throughout the design process. The Cadence Low-Power Solution is the industry's first complete flow that integrates logic design, verification, and implementation with the Si2-standard Common Power Format.

About Power Forward Initiative

The Power Forward Initiative, which has more than 25 member companies, is an industry initiative sponsored by Cadence that was formed in May 2006. It has the goal of enabling the design and production of more power-efficient electronic devices. The initiative includes companies representing a broad cross section of the design chain including system, semiconductor, foundry, IP, EDA, ASIC and design services companies. CPF was contributed by Cadence to the Si2 Low Power Coalition in December 2006 and CPF 1.0 is now available as an Si2 standard to the industry at large. The Initiative has recently published A Practical Guide to Low-Power Design — User experience with CPF which is aimed at educating the broad design marketplace in utilizing advanced low-power design techniques. The Guide is available free of charge at <http://www.powerforward.org>.

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